MAINTENANCE MANUAL

29.7-50 MHz TRANSMITTER/RECEIVER/SYNTHESIZER **ASSEMBLY 19D901630G1-6**

TABLE OF CONTENTS						
	Page					
DESCRIPTION	Front Cover					
CIRCUIT ANALYSIS	1					
System Control & Interface	1					
Transmitter	4					
Receiver Power Distribution	3 7					
	/					
MODIFICATION INSTRUCTIONS	8					
	0					
DUTLINE DIAGRAM	9					
ARTS LIST	13					
CHEMATIC DIAGRAM	19					

DESCRIPTION

The transmitter/receiver/system board (TRS) for DELTA-S provides all functions necessary for two-way communications in the 29.7-50 MHz range. The TRS board is provided in three groups. TRS board 19D901630G1 is used in radios operating in the 29.7-36 MHz range, 19D901630G2 operates in the 36-42 MHz range, and 19D901630G3 operates in the 42-50 MHz range. Maximum channel separation for each frequency split is shown in Table 1.

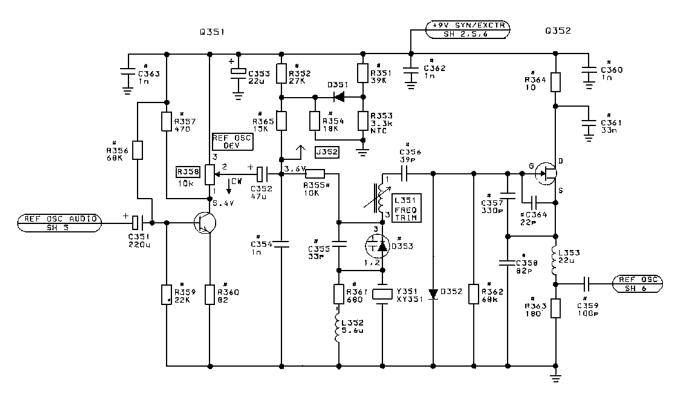
The TRS board contains the transmitter (less PA) and receiver circuitry, microcomputer and EEPROM, frequency synthesizer, audio processor, and voltage regulators. The microcomputer controls all system functions, supplies frequency data to the frequency synthesizer, and tone/code data to the Channel Guard option board. All RF frequencies are generated by the frequency synthesizer.

The transmitter PA is mounted on a separate board located along the side of the radio near the heat sink assembly.

Table 1 - Maximum Channel Separation

FREQUENCY	NO CENTER	W/CENTER	W/CENTER TUNING		
SPLIT (MHz)	TUNING	TUNING			
	TUNING	1011110	1 dB DEGRADATION	3 dB DEGRADATION	
29.7-36	0.5 MHz	1.0 MHz	1.5 MHz	1.75	
36-42	0.625 MHz	1.25 MHz	1.75 MHz	2.0	
42-50	0.75 MHz	1.5 MHz	2.0 MHz	2.5	





29.7-50 MHz REFERENCE OSCILLATOR/ MICROCOMPUTER BOARD

(19D901626, Sh. 7, Rev. 2)



Printed in U.S.A.

The TRS board is controlled by the control unit. The control unit interconnects with the radio by a power/control cable connected to front connector J601.

In addition to the normal radio functions, the microcomputer contains self diagnostic routines to aid in troubleshooting the radio. Included are internal tests of the microcomputer and input/output tests to assure proper operation of the data port and data bus. Diagnostic and Troubleshooting Procedures are included in the Service Section of this manual.

Centralized metering jacks are accessible from the top of the radio, and provide access for system, RF and PA metering.

CIRCUIT ANALYSIS

SYSTEM CONTROL & INTERFACE

The system control and interface circuits consist of the microcomputer, electrically erasable PROM (EEPROM), interface circuits for voltage shifting and protection and a watchdog timer. The EEPROM gives the user the capability to program or reprogram the radio's personality as desired. The EEPROM contains the receive and transmit frequency data, Channel Guard tone frequencies/digital codes and the CCT delay on a per channel basis.

NOTE

The EEPROM may be programmed serially through the front connect using the General Electric Universal Radio Programmer Model TQ2310.

The TRS board also provides access for parallel loading (through program connector J111) on a per channel basis using the General Electric Programmer 4EX22A10.

The microcomputer interfaces with the control unit through J601, responding to all user commands and control functions originating from the control unit. It provides the transmit and receive data to the frequency synthesizer, switching information for tone and digital Channel Guard, and the carrier control timer (CCT) function when the radio is in the transmit mode. A block diagram of the system control functions and frequency synthesizer is shown in Figure 1.

When the microphone is keyed the PTT line from the control unit goes low. This low is applied to the microcomputer through buffer Q701 and inverter Q711. Q701 is controlled by ignition switch A+. The ignition switch must be on and A+ applied to the base of Q701. Q701 must be turned on to permit keying of the transmitter.

The microcomputer immediately closes the antenna relay switch by applying a low level to DPTT at A701-28. The microcomputer then delays 15 milliseconds before the transmit 9V is switched on by applying a low level on TX ENBL at A701-32. This is done to guarantee that the antenna relay contacts are closed before the transmitter is energized. Once DPTT is at a low level the receive audio is muted. Buffers Q716 and Q717 provide DPTT to the audio control circuits, antenna relay, and the option board.

The TX ENBL line is controlled by microcomputer port 1 (bit 5 A701-32) through inverter Q718 and bilateral through inverter Q718 and bilateral switch U302C & D. A low level on A701-32 turns Q718 off, allowing the bilateral switches to be turned on and A- applied on the TX ENBL line. Inverter Q720 is also turned on during this time to inhibit the alert tone PTT.

Channel Selection

The microcomputer and EEPROM provide the radio with up to 32 independent transmit and receive frequencies. Each time the PTT switch is operated the microcomputer transfers channel data from the EEPROM and converts it to frequency data assigned to the selected channel. The frequency data is then loaded serially into the frequency synthesizer.

The microcomputer continually monitors the status of tri-state buffers U704A-D. These buffers are periodically turned off by a positive 5 volt, 1 millisecond pulse from A701-36. At the same time PROM power switch Q715 is turned on and applies +5 VDC to the EEPROM. When the buffers are turned on channel select data is 10aded into input/output ports of the microcomputer through ports P20-P23. Power is then applied to the EEPROM and the tri-state buffers are turned off. The microcomputer converts the channel select data into address information, accesses the EEPROM, and receives the frequency data stored in the addressed location. This data then passes through the I/O ports of the EEPROM and P20-P23 of the microcomputer. The conversion process is repeated eight times in rapid succession (eight locations are required for each channel) and the data loaded serially into the frequency synthesizer using the clock and data lines. This data also includes Channel Guard information, if present, and carrier control timer information on a per channel basis. A 4-millisecond channel change pulse from port P16 of the microcomputer is also sent to the frequency synthesizer to speed up channel acquisition.

Also considered at this time is the status of frequency bit 5 (FB5) and the PTT line A701-38. The status of the PTT line is used to determine if the radio is in the transmit or receive mode to assure the right frequency data is accessed. The status

of FB5 also determines which EEPROM contains the requested data.

A second EEPROM is required if more than 16 channels are provided. The second EEPROM is plugged directly into pins extending above the top of the first EEPROM. Programming Jack J711 may be used to program both PROMS (using PROM Programmer 4EX22A1O).

Diodes D718A and B and D719A and B provide spike protection for the microcomputer. D717A and B provide spike protection for the EEPROMS.

Watchdog Timer

The watchdog timer, consisting of a digital counter U703-A and Q714, monitors the operation of the microcomputer and U703A generates a reset pulse in the unlikely condition that the microcomputer gets lost and does not execute the software properly. A 6 MHz crystal, Y701, steps the microcomputer through the software. As programmed in software a random pulse appears at A701-35 and is applied to the base of inverter Q714, momentarily turning it on and inhibiting any reset pulse from timer U703-A. If the timer does not receive any inputs for a specified period of time, Q714 turns off and U703-A times out and applies a reset pulse to pin 4 of the microcomputer. The watchdog reset will normally restore the microcomputer to normal operation so that only one pulse will occur. In the event the microcomputer is not restored to normal operation a 6 Hz square wave will appear on the reset line and the indicator D713 (now unlocked) will turn on. Refer to the Service Section of this manual and run the self diagnostics routine to determine the problem.

Advance Change Pulse

The advance change pulse is received from the option board through connector J601 and applied to the microcomputer interrupt port A701-6 through inverter Q713. The advance change pulse is required in radios equipped with PSLM. When a call is received on a priority channel the advance change pulse interrupts the microcomputer forcing it to service immediately the I/O circuits. The tri-state buffers are turned on and new channel select information read in.

Carrier Control Timer

The carrier control timer function is executed by the microcomputer under software control on a per channel basis. When the programmed time has lapsed an alert tone is generated from P13 (A701-30) on the microcomputer, applied to the audio PA and heard on the speaker. The CCT may be programmed for 1, 2, or 3 minutes or disabled (not programmed).

Voltage Translation

Inverter buffers U707D-F, and Q721 translate the 5 VDC levels required by the microcomputer to the +9 VDC level used by the frequency synthesizer. Inverter Q719 restores clock polarity.

Channel Guard

The Channel Guard encode and decode functions are implemented in the microcomputer under software control. The microcomputer provides digital and/or tone Channel Guard with STE.

If the radio is in the receive mode, the Channel Guard tone/code is hard limited and inputted into the microcomputer through A701-29 (LIM CG Tone Decode). If the correct tone code is present, the receiver is opened by the RX MUTE line. If the radio is in the transmit mode, the microcomputer generates the Channel Guard tone using WALSH BIT 1 and WALSH BIT 2. Those outputs are summed together and filtered on the optional Channel Guard board to generate a smooth sinewave for tone Channel Guard or a digital waveform for digital Channel Guard.

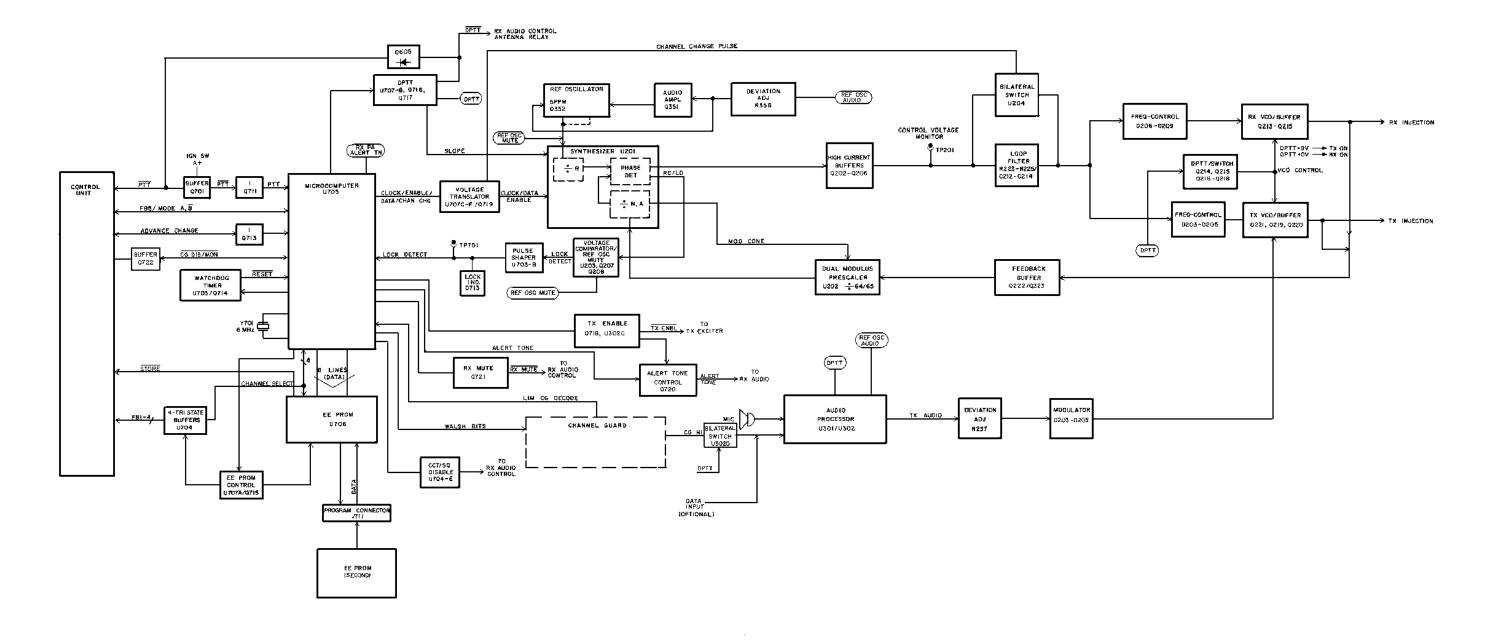
Frequency Synthesizer

The frequency synthesizer receives clock, data, and control information from the microcomputer and from this generates the TX/RX RF frequencies and provides frequency lock status to the microcomputer. It consists of synthesizer chip U201, low and high current buffers, loop filter, TX & RX voltage controlled oscillators (VCO's), feedback amplifiers, dual modulus prescaler, and reference oscillator. The VCO's are locked to the reference oscillator by a single direct divide synthesize loop consisting of the feedback buffer, prescaler, and synthesizer. The VCO's operate over a frequency range of 29.7 MHz to 50 MHz.

Reference Oscillator

The reference oscillator consists of a 5 PPM oscillator, an audio amplifier and temperature compensation network. The standard reference oscillator frequency is 13.2 MHz.

The 5 PPM oscillator is a standard Colpitts circuit using a FET transistor Q352 and fundamental crystal Y351. Oscillator output is typically 0.7 VPP. Audio deviation is set by R358 for ± 1 kHz.



The temperature compensation network consists of R351-R354 and D351. R353 is a thermistor having a negative temperature coefficient. Its resistance increases with a decrease in temperature. The output voltage of the temperature compensator varies the voltage applied to varicap D353 to maintain the oscillator frequency within ± 5 PPM.

The output of the reference oscillator is applied to the synthesizer input, XI along with Q203 and Q205.

Synthesizer

Synthesizer U201 contains a programmable reference oscillator divider (+R), phase detector, and programmable VCO dividers (+N, A). The reference frequency, 13.2 MHz from the reference oscillator is divided by a fixed integer number to obtain a 5 kHz channel reference for the synthesizer. The internal phase detector compares the output of the reference divider with the output of the internal +N, A counter. The +N, A counter receives as its input the VCO frequency divided by the dual modulus prescaler and programmed by the microcomputer. This comparison results in a \pm error voltage when the phases differ and a constant output voltage when the phase detector inputs compare in frequency and phase.

If a phase error is detected an error voltage is developed and applied to the high current buffers and loop filter to reset the VCO frequency. The count of the +N, A counters is controlled by the frequency data received on the clock and data lines from the microcomputer. Thus, when a different channel is selected or when changing to the transmit or receive mode an error voltage is generated and appears at the phase detector output, ANO, causing the phase locked loop to acquire the new frequency.

The enable pulse from the microcomputer enables the synthesizer and allows frequency data to be internally stored.

DC Offset and High Current Buffers

DC offset buffers O203, O205 and O206 receive the error voltage from the synthesizer and increases this level by 1.8

VDC to extending the operating range of the high current buffers. When the PLL is off frequency due to a channel change or frequency drift the error voltage from the synthesizer (ANO) rises or falls turning Q206 on or off. Q206 controls the DC offset buffers Q203 and Q205 and high current buffers Q202 and Q204. Q202 and Q204 complete a high current rapid charge path for C212-C214. Q205 and Q206 provide the rapid discharge path.

As the error voltage decreases Q206, Q203 and Q205 turn on completing a discharge path for C212-C214 through bilateral switches U204A-D. When the error voltage goes positive Q203, Q205 and Q206 are turned off, allowing C212-C214 to charge through Q202 and R223-R225. U204 is turned on for 4

milliseconds each time a channel is changed in receive or when changing from transmit to receive. The time is 20 milliseconds when in transmit.

Loop Filter

The loop filter consists of R223-R225, and C212-C214. This filter controls the bandwidth and stability of the synthesizer loop. Bilateral switch U204 is controlled by the 4 millisecond, 9 volt channel change pulse. When the channel change pulse is present the bilateral switch shorts out the low pass filter greatly increasing the loop bandwidth to achieve the 4 millisecond channel acquisition time required for PSLM. The low pass filter removes noise and other extraneous signals internal to the synthesizer chip.

The output of the filter is applied to the varicaps in the transmit and receive VCO's to adjust or correct the VCO frequency.

Receiver Voltage Controlled Oscillator

The Receiver VCO consists of a low noise JFET oscillator, Q213, followed by high gain buffers Q214 and Q215. These buffers prevent external loading and improves power gain. The VCO is a Colpitts oscillator with the various varactors, capacitors and inductors forming the tank circuit. Capacitor C220 allows manual adjustment of the VCO across the frequency split. The varicaps provide voltage controlled frequency adjustment of about 3 MHz. The VCO is switched on and off under control of the DPTT line. When the DPTT line is low the Receiver VCO is turned on (Q218 is on). Oscillator output is typically +10 dBm. RX VCO lock time is 4 milliseconds maximum.

Transmitter VCO

The Transmit VCO is basically the same as the Receiver VCO except that coil L211 is tuned to provide an operating range of approximately 8 MHz, depending on which frequency split the radio is operating on. The varactors provide a voltage controlled adjustment range of approximately 3 MHz. The high gain series buffers Q219 and Q220 provide a typical output of +10 dBm. Transmit audio is applied to deviation adjustment control R237. Deviation is set for 4.5 kHz. TX VCO lock time is 20 milliseconds maximum.

TX VCO control switch Q216 and Q217 turn the Transmit VCO on when DPTT is high. Q216 is off, Q217 is on.

The use of two VCO's allows rapid independent selection of transmit and receive frequencies across the frequency split.

VCO Characteristics

The synthesizer has two VCO's or voltage controlled oscillators. The VCO frequency is directly related to a control voltage generated by the synthesizer circuitry and must remain within specified limits for the synthesizer to function properly. The RX VCO typically will increase in frequency about 4 MHz when the control voltage moves from its lower limit to its upper limit. The TX VCO moves about 6 MHz for the same situation. By tuning the coil for the TX VCO or the capacitor in the RX VCO, the same control voltage frequency spread can be moved up or down through the full range of frequencies that the radio operates on.

In order to maintain the excellent selectivity and hum and noise performance of the radio, the frequency range that the VCO's can be voltage tuned must be kept to a minimum. This requires that all the available voltage range be fully utilized. The alignment procedure, therefore, instructs the user to accurately set the control voltage to the upper limit of the voltage range at the highest frequency channel.

NOTE _____

Going too high with the voltage setting at the highest frequency channel may cause problems over temperature extremes as the VCO's will drift slightly. Set the voltage too low and you may not remain within the required lower voltage limit as you cover the radio's maximum two frequency spread.

If the required frequency spread is less than the maximum two frequency spread, then there are no restrictions on setting the lowest and highest frequencies within the required voltage limits.

The minimum tuning requirement of the VCO's is to cover the proper frequency range. For instance, to cover 29.7 to 50 MHz the VCO must be tunable such that at 29.7 MHz the control voltage is at least greater than or equal to the lower voltage limit, and at 50 MHz the voltage must be less than the upper limit. If the control voltage can be tuned higher than the lower limit at 29.7 MHz, this simply means that you can program channels below 29.7 until you finally run into the lower voltage limit. When tuning the VCO's to a channel close to 50 MHz, the control voltage may not reach the upper control voltage limit. This is normal for some radios and is due to the tolerances on the many capacitors in the VCO. Even though it takes very little change in capacitance to shift the VCO frequency range a few megahertz, this variation has been carefully compensated for by increased tuning range for the VCO. Therefore, if you tune to 50 MHz, you may not achieve the maximum control voltage for all radios, but you will always be greater than the lower voltage limit.

The dual modulus prescaler completes the PLL feedback path from the synthesizer to loop filter, to the VCO's and feedback buffers and then back to the synthesizer through the prescaler. The prescaler divides the VCO frequency by 64 or 65 under control of MOD C from the synthesizer. The output of the prescaler is applied to the synthesizer where it is divided down to 5 kHz by an internal +N, A counter and compared in frequency and phase with the divided down frequency from the reference oscillator. The result of this comparison is the error voltage used to maintain frequency lock. The +N, A counter is controlled by data received from the microcomputer. Depending on the operating frequency, the DC voltage at TP201 should be within the range 3.5 to 7.5 VDC when the PLL is locked.

The lock detect circuit consists of comparator IC U203, diodes D201 and D202, and reference oscillator mute switch O207 and O208. It is used to quickly synchronize the phase relation of the divided down VCO frequency and the reference oscillator if the loop loses lock. It also provides a fast lock detect signal to the microcomputer to turn on the outof-lock indicator. If a large change in frequency is required the ramp capacitor output (RC) of the synthesizer may increase to near 7.5 VDC and cause the comparator output to decrease. This decrease in voltage turns Q207 off and allows Q208 to be turned on by the positive LD line from the synthesizer. Thus Q208 disables the reference oscillator and allows the PLL to be brought back to synchronization rapidlv.

Note that the RX & TX VCO's have totally different tuning adjustment devices. The TX VCO will tune as any coil will by reaching a peak voltage setting at the 50 MHz frequency, assuming that the peak falls within the control voltage limits of the VCO. The RX VCO uses a multi-turn trimmer capacitor which lowers the VCO frequency linearly with clockwise turns of the screw-type slotted piston. Unlike the coil used in the TX VCO, the trimmer C does not peak but simply reaches a maximum setting (lowest frequency is maximum setting) and stops turning. The 50 MHz receive channel should have a control voltage greater than the lower limit. The trimmer cap is a very high quality device which allows the RX VCO to always have consistent state-of-theart noise performance necessary for a high quality synthesized radio.

Feedback Buffers

The RX injection and TX injection voltage output from the RX VCO and TX VCO are supplied to the receiver mixer and the exciter respectively and to the feedback buffers. Buffering is provided by Q222 and Q223 and the output applied to dual modulus prescaler U202.

Dual Modulus Prescaler

Lock Detect

If a large frequency error exists the LD positive lead from the synthesizer will carry negative spikes to the microcomputer through D202B to activate the lock indicator circuit. Pulse shaper U703 is a one-shot multivibrator which increases the pulse width to span 1 computer cycle. Q207 is turned on, keeping Q208 off thereby preventing Q208 from muting the reference oscillator.

TRANSMITTER

The transmitter section of the TRS board includes the audio processor and exciter. The power amplifier is contained on a separate board adjacent to the TRS board and next to the heat sink assembly. Information related to the PA is included in a separate insert. Figure 2 is a transmitter block diagram showing the exciter and PA. The audio processor is shown in Figure 1.

Audio Processor U301

The audio processor provides audio pre-emphasis with amplitude limiting and post limiter filtering and a total gain of approximately 24 dB. Approximately 20 dB gain is provided by U301B and 4 dB by U301A.

The 9 Volt regulator powers the audio processor and applies regulated 9 volts to a voltage divider consisting of R303, R313, R308 and R312. The +4.5 V output from the voltage divider establishes the operating reference point for operational amplifiers

U301B and U301A. C302 provides an AC ground at the summing input of both operational amplifiers.

The voltage divider and diodes D301 and D302 provide limiting for U301B. Diodes D301 and D302 are reversed biased at +1.7 VDC. Voltage divider network R303, R308, R312 and R313 provides +6.2 VDC at the cathode of D301 and +2.8 VDC at the anode of D302. The voltage junction of D301 and D302 is 4.5 V. C308 and C312 permit a DC level

change between U301B-7 and the voltage divider network for diode biasing.

When the input signal to U301B-6 is of a magnitude such that the amplifier output at U301B-7 does not exceed 4 volts PP, the amplifier provides a nominal 20 dB gain. When the audio signal level at U301B-7 exceeds 4 volts PP. diodes D301 and D302 conduct on the positive and negative half cycles providing 100% negative feedback to reduce the amplifier gain to 1. This limits the audio amplitude at U301B-7 to .5 volts PP.

Resistors R309, R310 and R311 and C311 comprise the audio pre-emphasis network that enhances the signal-to-noise ratio. R311 and C311 control the pre-emphasis curve below limiting. R306 and C311 control the cut-off point for high frequency pre-emphasis. As high frequencies are attenuated, the gain of U301 is increased.

Audio from the microphone is coupled to the audio processor through C307 and R307.

The amplified output of U301B is coupled through R305, C306, R314, R315 and bilateral switch U302-A to a second operational amplifier U301A. The bilateral switch is controlled by the DPTT line so that TX audio is transmitted only when the PTT switch is pressed.

The Channel Guard tone input is applied to U301A-2 through J603-15, R301 and bilateral switch U302A. The CG tone is then combined with the microphone audio at U301A. U301-A provides a signal gain of approximately 4 dB.

A post limiter filter consisting of U301A, R314-R316, C309 and C313 provides 12 dB per octave roll-off. R305 and C305 provide an additional 6 dB per octave roll-off for a total of 18 dB. The output of the post limiter filter is coupled through R236 to the transmitter VCO.

TX enable switch U302-B shorts out operational amplifier U301-A when the radio is in the receive mode. The TX EN-ABLE signal is generated by the microcomputer when the PTT switch is released and is less than 2.7 VDC in the receive mode.

SERVICE NOTE

Some resistors have a tolerance of 1%. This tolerance

must be maintained to assure proper operation of the post

Provisions for data input are provided by J303.

limiter filter. Use exact replacements.

The second metering point at J101-9 monitors the collector voltage of amplifier Q102, through R111, R118 and C110. This point typically is 0.45 V on the GE test set.

The third metering point at J101-8 monitors the collector voltage of driver Q102. The metering network consists of R112, R119, and C108. The relative exciter power output can be read at the test jack on the power amplifier assembly.

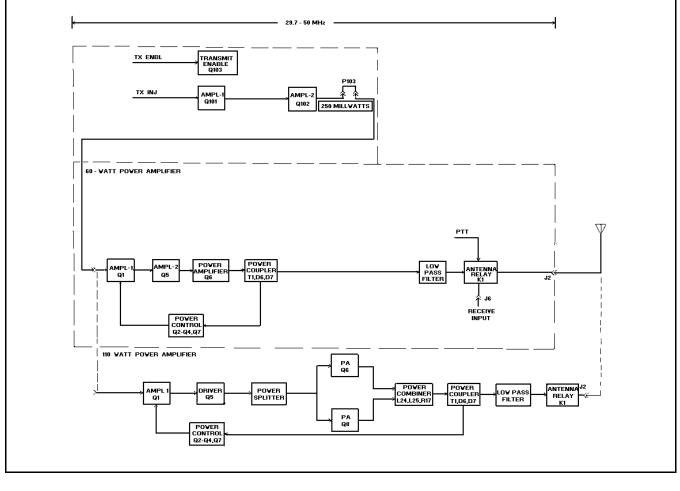


Figure 2 - Transmitter Block Diagram

Exciter

The exciter consists of two broadband fix tuned amplifier stages operating over a frequency range of 29.7-50 MHz. An attenuator pad (R101-R103) at the input of the exciter provides a constant load for the VCO and attenuates the signal from the VCO to approximately 18 dBm. The exciter amplifies the 18 dBm signal from the VCO to provide 250 milliwatts drive to the power amplifier.

The injection frequency input from the TX VCO is applied to the base of amplifier Q101 through an attenuator pad and impedance matching components C101, C102 and L101. The impedance matching network matches the VCO output to the base of Q101. R106 and R107 set the bias voltage for the Q101. Collector voltage is applied direct from the +9V SYNTH/ EXCTR line through TX ENBL switch. Q103 and collector feed network L102 and R109. C103 provides noise decoupling.

The output of Q101 is coupled to the base of transmitter driver Q102 through C106 and impedance network C109, L103 and R113. The 250 milliwatt output of Q102 is coupled to the power amplifier board through 50 ohm impedance matching network C116, L105, C117, and service plug P103 and output plug P101.

Collector voltage for Q101 is supplied by +9V SYNTH/ EXCTR through 9V TX switch Q103. Q103 is controlled by TX ENBL from the microcomputer. When TX ENBL is low Q103 is turned on providing voltage to amplifiers Q101. When TX ENBL goes high (receive mode) Q101 is turned off, preventing any interference by the TX VCO frequencies.

Collector voltage for driver Q102 is supplied from the +9V SYNTH/EXCTR source through R114 and R115 and collector feed network L102 and R109.

P101 consists of a pin soldered to the end of the microstrip. The outer shield consists of a hole in the casting through which the pin connects to the PA.

Three exciter metering points are accessible at RF metering jack J101. The first metering point at J101-10 monitors the emitter voltage of Q101 through metering network C104, R117 and R110. Typical reading is 0.65 V on the GE test set.

SERVICE NOTE

J103 can be used for troubleshooting purposes and measuring the RF output level of the exciter.

The exciter is energized by pressing the PTT switch. A regulated 9 volts is present on Q102 when the radio is turned on. It is normal to read collector voltage at J101-9 when the transmitter is not keyed.

Capacitors C112, C114 and C115 isolate the exciter board from vehicle ground for operation in vehicles with positive or negative ground.

RECEIVER

The FM receiver used in DELTA-S radios is a single conversion receiver using 10.7 MHz as the IF frequency. Adjacent channel selectivity is provided by three 4-pole crystal filters.

The nine volt regulator supplies power to all receiver circuits except the audio PA IC's which receive power directly from the A+ supply through the power on switch. A block diagram of the receiver is shown in Figure 3.

All receiver circuitry is mounted on the TRS board and consists of:

- Receiver Front End
- LO Injection Amplifier
- Diode Mixer
- 10.7 MHz IF Circuitry
- Limiter/FM Detector
- Audio PA
- Squelch

Receiver Front End

The RF signal is coupled through a 2-pole LC filter (L402 and L403) to a common gate JFET pre-amplifier, O401. After amplification by O401, the RF signal is coupled through a 4-pole LC filter and T401 to the double-balanced diode mixer D401-D404.

RX Injection

The injection frequency from the synthesizer (5-15 dBm) is applied to the base of injection buffer/amplifier Q406 through 50 ohm microstrip Z403. The output of Q406 is filtered by a 2-pole LC filter (L415, L416) to remove spurious signals and coupled to the diode mixer through T402.

Injection metering (INJ METER) is taken from the emitter of injection amplifier Q406 and metered at J101-3 (position H on the Test Set). The reading is typically 0.4 volts with injection and 0.1 volts without injection. The synthesizer frequency may be monitored at C435.

Mixer

The diode mixer, D401-D404, provides low input impedance, spurious protection, and an output relatively free of harmonics (low in intermod products).

Receiver RF from the pre-amplifier and LC filters is applied across D402 and D404 of the diode mixer. Injection voltage from the frequency synthesizer is amplified by injection amplifier Q406, filtered by 2-pole LC filter, L415 and L416, and applied to the diode mixer across D401 and D403. The 10.7 MHz output is coupled from the center tap of T401 through C420 and R405 to the source input of IF AMPL Q402. Q402 is a JFET amplifier/buffer stage. The output of the JFET buffer is coupled through C421 to the optional noise blanker (W401 removed) or through impedance matching networks L411, L412, and associated circuitry (bypassing IF blanking FETS Q403 and Q404) to a 4-pole XTAL bandpass filter (W401 connected).

The highly-selective crystal filter consisting of Z401 and Z402 provides the first portion of receiver IF selectivity. The output of the filter is coupled through a second impedance matching network (C431, R414 and L413) to G1 of IF amplifier O405.

Voltage to the drain of Q405 is supplied from the +9V RX supply through L501, L502, R415, R418 and L414.

IF & Detector Stages

IF amplifier Q405 is a dual-gate low-noise MOS FET amplifier. The filter output is applied to gate 1 of the amplifier, and the output is taken from the drain. The biasing on gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain. The output of Q405 is matched into a second 4-pole crystal filter by tuned circuit L414, C433 and R419. The output of the crystal filter is applied to IF amplifier IC U501 through impedance matching network L507, C502, C503, and R501.

U501 provides approximately 55 dB of gain. Following U501 is a third 4-pole crystal band-pass filter (Z503 and Z504) which provides the final stage of IF selectivity.

IF signal from the 4-pole crystal filter is applied to the IF amplifier/limiter/FM detector IC (U502) through impedance matching network L508, C511, C512, and R503. The amplifier provides approximately 80 dB of gain to insure that the signal is well into limiting.

U502 also contains the quadrature FM detector. The single-tuned LRC network, consisting of L509, C515, C516, and R504, provides the 90° phase shift necessary to produce the recovered audio. The low level detected audio is applied to audio preamplifier U603-B.

The metering for the FM detector and IF amplifier is provided by the red systems metering jack J602-1 and 10 respectively. The metered outputs are taken from U502.

Audio And Squelch Circuits

Audio

Received audio from the FM detector is applied to the input of audio preamplifier U603-B. The audio output level of the audio preamplifier is adjusted by Volume/Squelch HI level control R629 for 300 millivolts RMS. The audio is then applied to the volume and squelch (optional) controls in the control unit through front connector J601-7.

Audio is returned on VOL ARM through J601-8 and applied to audio gate (bilateral switch) U605-B. The audio gate is controlled by DPTT (delayed Push-To-Talk) and PA KEY/CCT PA ENBL through Q603 and is turned on when the control input (pin 5) exceeds 7 VDC. The gate is turned off when the control input is less than 2 volts. Receipt of an on frequency signal (if present) with sufficient signal to noise level and the correct Channel Guard frequency will cause the audio control circuit to apply +9 volts to U605-B turning the audio gate on.

Audio from the audio gate is applied to the de-emphasis network consisting of a 2-pole low-pass filter (U603D), a 2-pole high pass filter (U603C) and associated circuitry. The low pass filter consisting of R614, R615, C606, C607 and U603-D provides a 6 dB per octave roll-off between 300 and 3000 Hz. C608, C609, R617, R616, R618, R619 and U603-C form a 2-pole high pass filter that attenuates frequencies below 300 Hz. The audio output from the de-emphasis network is applied to the non-inverting input of the audio power amplifier. The audio power amplifier is comprised of U601, U602, and associated circuitry, and forms a bridge amplifier to provide 12 watts (6.93 VRMS across a 4 ohm load) of audio output power at radio output metering terminals J602-6 and 7. The output of U601 is applied to one side of the speaker and through a voltage divider (R621 and

The squelch circuit monitors noise on the VOL/SO HI input line and allows the receiver to be unmuted when an on frequency signal reduces the noise level below the squelch threshold setting.

The squelch circuit consists of a 3-pole high pass filter, an averaging detector, DC amplifier, and a Schmitt trigger. The high pass filter, consisting of R601-R603, C601-C603, and U604-C, removes all voice signals from the VOL/SQ HI input and couples noise to U604-D.

Noise in the 6-8 kHz range is applied to the averaging detector consisting of U604-D and associated circuitry. The noise is rectified and filtered by U604-D, R608, and C605 to provide an average DC output level proportional to the noise input.

The average DC level is amplified by U604A to a level ranging from 0 to 6.0 VDC, and applied to the non-inverting input of the Schmitt trigger, U604B. The inverting input of U604B is referenced to 4.5 VDC. U603A provides the stable 4.5 VDC reference voltage.

When the DC level exceeds 4.5 VDC, Schmitt trigger U604B switches and provides a positive voltage to the CAS (Carrier Activity Sensor) and RUS (Receiver Unsquelched Sensor) control transistors in the audio control circuits. The Schmitt trigger will remain on until the threshold level falls below approximately 4.3 VDC. This difference in voltage between the firing point and turn-off point provides sufficient hysteresis to eliminate "bubbling" -- i.e., noise popping in the speaker. The "bubbling" would normally be caused by transitional changes in the DC level around the reference point which allows the receiver to be unmuted. The hysteresis is provided by R611 and R612.

When an on frequency signal is received, there will be little or no noise present at the squelch input. This results in an absence of voltage at the output of the squelch circuit Schmitt trigger, allowing the receiver to be unmuted.

R622) to the inverting input of U602. The output of U602 is equal in amplitude but 180° out of phase with U601 and is applied to the other side of the speaker. U601 and U602 provide a balanced pushpull output to the speaker. The gain of U601 and U602 provide a balanced pushpull output to the speaker. The gain of U602 is determined by the value of R623 and R624.

Squelch Circuits

The 300 millivolt output of the audio preamplifier is applied to the squelch circuit through the variable squelch control (optional) in the control unit or the fixed squelch control. The squelch control sets the noise threshold level required to operate the squelch circuit. When the noise falls below the threshold level, the receiver is unmuted.

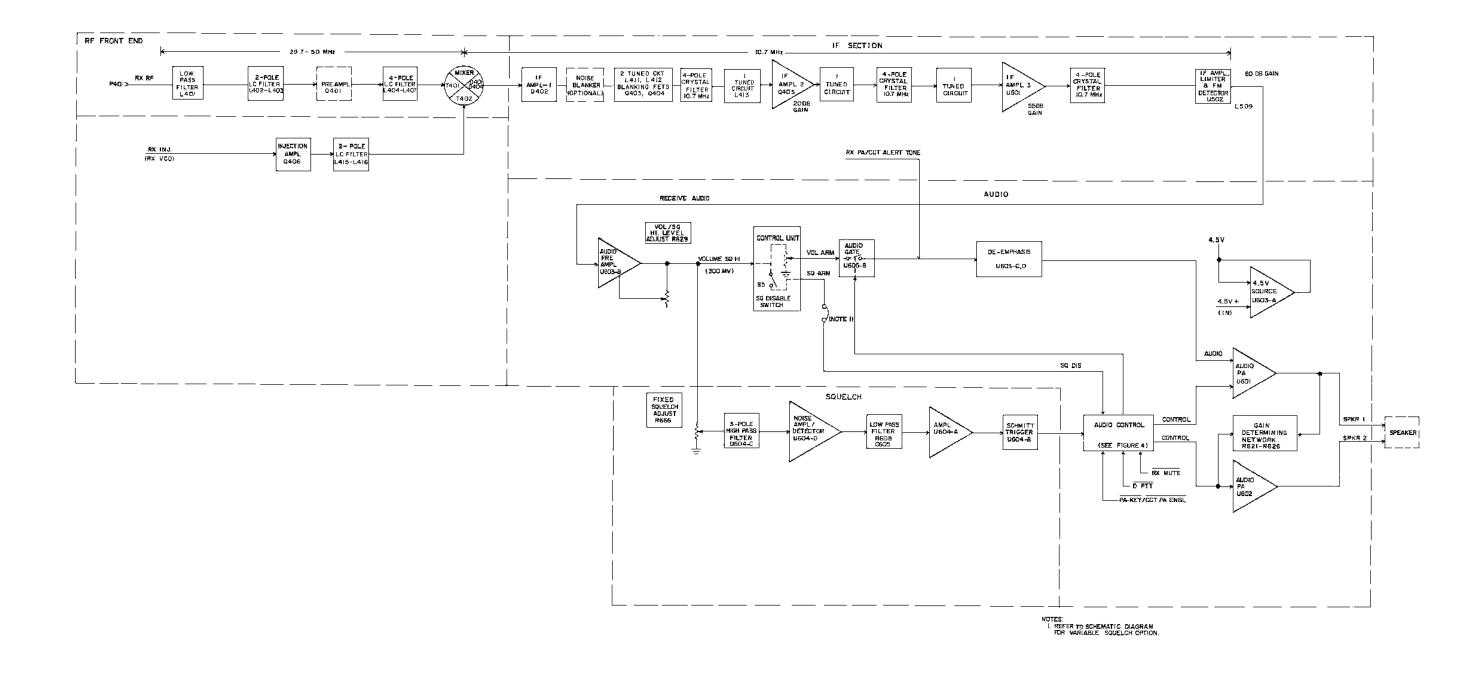


Figure 3 - Block Diagram Receiver

Audio Control

The audio control circuits shown by Figure 4 control the operation of the audio gate (U605-B) and the final audio PA and consists of Q601-Q606, inverter U605-C and associated circuitry. The audio control circuit inputs consist of DPTT (Delayed Push-To-Talk), RX MUTE (Receiver Mute), PA KEY/CCT SQ DSBL (Public Address Key/Carrier Control Timer Squelch Disable), and the output of the squelch circuit.

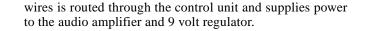
When an on frequency signal with the correct Channel Guard Tone is received, CAS control transistor Q601 and RUS control transistor Q602 are turned off by the absence of a positive voltage at their bases. The CAS line from the collector of Q601 rises to +9 VDC and is supplied to J601-12 and option connector J603-7.

The collector of RUS Transistor Q602 also rises to +9 VDC and turns on inverter U605-C. A- is then applied to the base of inverter Q603, turning it off and allowing its collector to go high. The positive voltage on the collector is applied to audio gate U605-B, turning it on. Q604 is biased on but has no affect on audio switches Q605 and Q606. The base of the transistors are parallel connected to the output of audio control switch (U605C-9) which is at A-. Therefore Q605 and Q606 are both turned off, allowing the audio PA's to turn on and complete the audio path to the speaker.

When the microphone is keyed, the PTT/DPTT input is low. This low is applied to audio gate U605-B through D603-B, turning U605-B off. It is also applied to audio control switch U605-C (through D601B) turning it off. Q603 is also off and Q604-Q606 are on. Q605 and Q606 turn off audio PA's U601 and U602.

POWER DISTRIBUTION

Battery supply A+ enters the radio through the front connector at J601-37. A- enters through J601-21. Figure 5 is a block diagram of the power distribution system. Two heavy connections are provided for transmit A+ and transmit A- and connect to two busses. The busses are connected to the PA through a special feed through arrangement. A second set of



9 Volt Regulator

The 9 volt regulator receives the 13.8 VDC supply voltage and regulates it down to +9 VDC. The regulated voltage is then distributed throughout the radio. The 9 volt regulator consists of pass transistor Q705, shunt regulator IC U701, as well as Q703 and Q704. Normally all transistors are turned on except Q704 which turns on only when the 9 volt output is shorted to ground.

As the input voltage increases so does the output of the regulator begin to increase. This increases the voltage on U701 from pin 1 to ground. The shunt regulator IC U701 tries to maintain the voltage at pin 2 to about 2.5 volts by sinking more current into its pin 3. This lowers the voltage at pin 3 and thus reduces the current flowing through D701 and Q703. When this current decreases it causes Q705 to provide less current to the 9 volt output and brings the 9 volt output back down where it belongs. When the input voltage decreases then the opposite occurs.

If the 9 volt output were shorted for any reason then Q704 would forward conduct causing its base voltage to sit around 1.4 VDC. That voltage is low enough to cause D701 in conjunction with Q703 to turn off shutting down the regulator until the short is removed. C701 thru C705 are for RF bypassing. R703 is provided as an adjustment of the 9 volt regulator output level.

CAUTION



The CMOS Integrated Circuit devices used in this equipment can be destroyed by static discharges. Before handling one of these devices, the service-man should discharge himself by touching the case of a bench test instrument that has a 3-prong

power cord connected to an outlet with a known good earch ground. When soldering or desoldering a CMOS device, the soldering iron should also have a 3-prong power cord connected to an outlet with a known good earth ground. A battery-operated soldering may be used in place of the regular soldering iron.

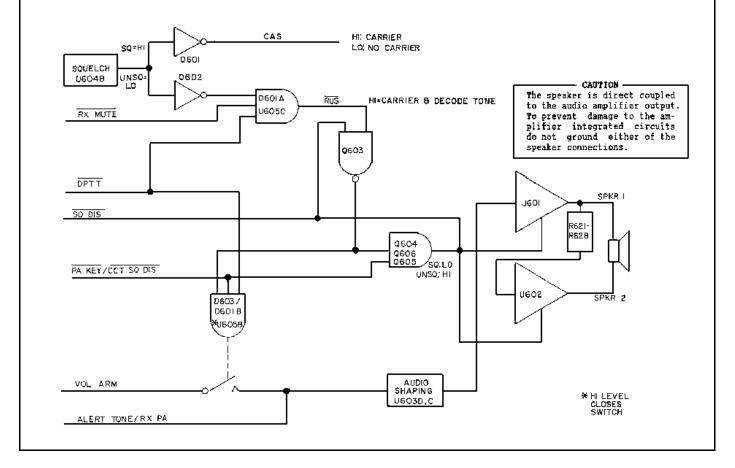
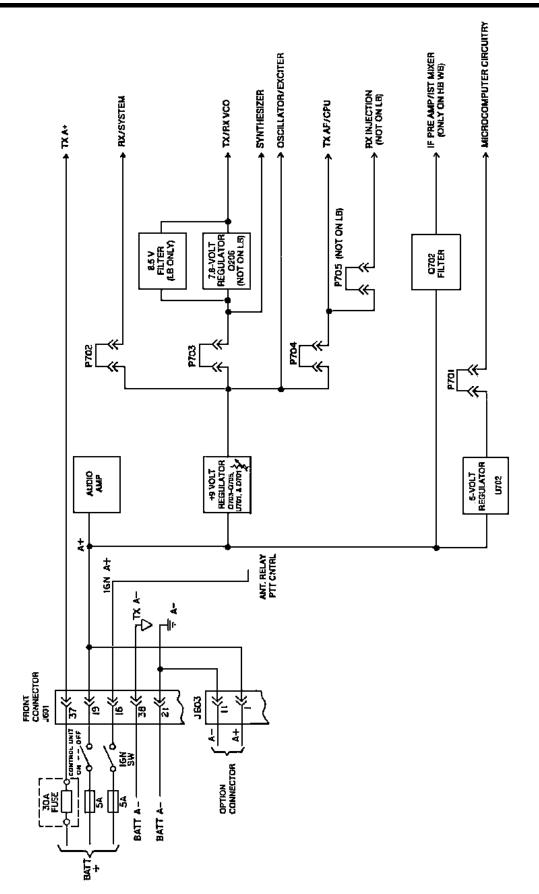


Figure 4 - Audio Control

LBI-31535



MODIFICATION INSTRUCTIONS

This modification instruction covers the installation of Mod Kit 19A704915G1 along with shielded power/control cable and modified radio bottom cover 19B800686G4 to a Delta S/SX mobile radio to provide improved RFI performance where antenna is in close proximity to power/control cable.

PARTS REQUIRED

- Shielded power/control cable
- Modified radio bottom cover 19B8000686G4
- Modification Kit 19A704915G1 consisting of:

Filter Board Assembly	19B801399G1
Modified Plastic Spacer	19B801402G1
#12-24 Slotted Head Machine Screw	
#12 External Tooth Lock Washer	N403P21C6
Aluminum Offset Spacer	19A704893P2
M3.5 x 10 Thread Forming Screw	

TOOLS REQUIRED

- #12-24 NC Fluted Taper Tap and Tap Handle
- #15 & #30 TORX[®] Screwdrivers
- Flat Blade Screwdriver

PROCEDURE

Figure 5 - Power Distribution

- STEP 1 Remove radio from vehicle to a convenient work area. Tap existing hole on right front corner of radio frame using #12-24 NC fluted taper tap.
- STEP 2 Remove radio top cover and plug in filter board assembly 19B801399G1 to top row of J60l pins 26 thru 34 taking care to align connector correctly with rubber pad positioned towards front of radio. Mount ground lead as shown using M3.5 x 10 thread forming screw supplied or under screw retaining channel guard board. (See Figure 6) replace top cover.
- STEP 3 Remove and discard radio bottom cover. Remove and discard plastic block at J601 front connector and replace with modified plastic block 19B80I402G1. Install modified radio bottom cover 19B800686G4 with notch in gasket towards front of radio (cover is marked on outside "This End to Front").
- STEP 4 Remove power/control cable from vehicle if installed and install new shielded power/control cable. Connect shield to hole tapped in radio frame using #12-24 slotted head screw N37Pl90l2B, external tooth lock washer N403P21C6 and spacer 19A704893P2. See Figure 6.

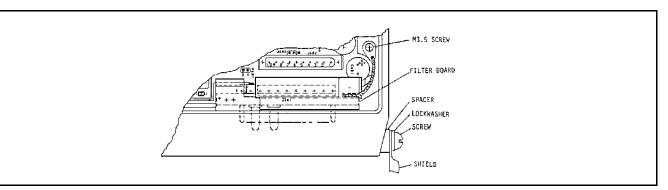
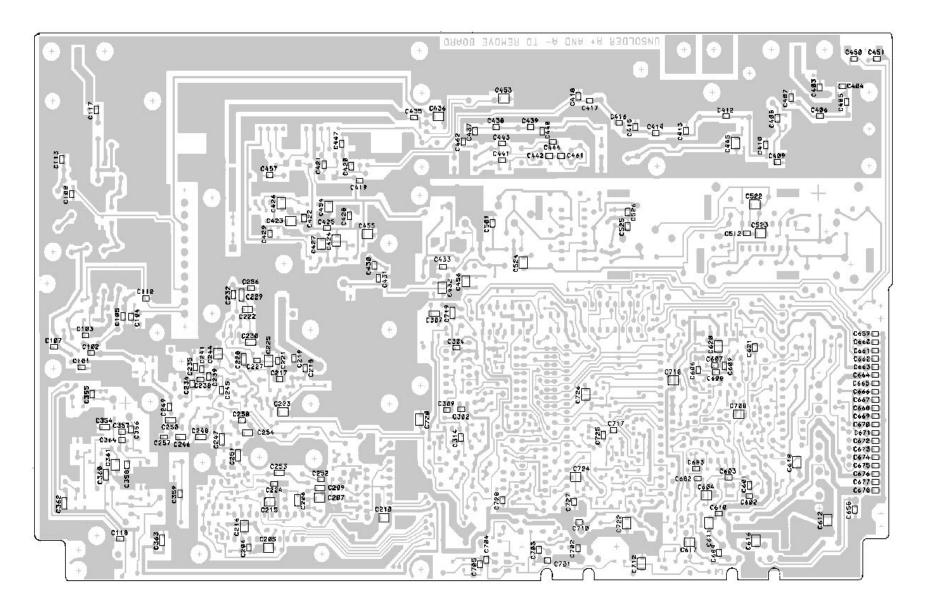


Figure 6 - Shielded Power/Control Cable Installation

8

OUTLINE DIAGRAM

CHIP COMPONENT LOCATION



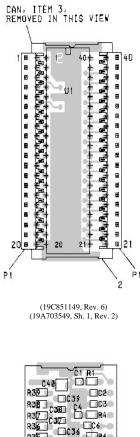
LEAD IDENTIFICATION FOR ALL TRANSISTORS NOT OTHERWISE IDENTIFIED

s IN-LINE TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.



LBI-31535



 C1 R1

 C40

 R30
 C37

 C38
 C4

 C38
 C4

 R37
 C36

 C38
 C4

 C38
 C36

 R35
 C37

 C38
 C31

 R32
 C32

 C39
 C12

 R32
 C39

 C18
 C29

 R37
 C29

 C21
 C19

 R37
 C23

 C24
 C17

 R25
 C22

 C19
 R26

 C21
 C19

 R32
 C21

 C19
 R32

 C21
 C19

 R32
 C21

 C19
 R32

 C21
 C19

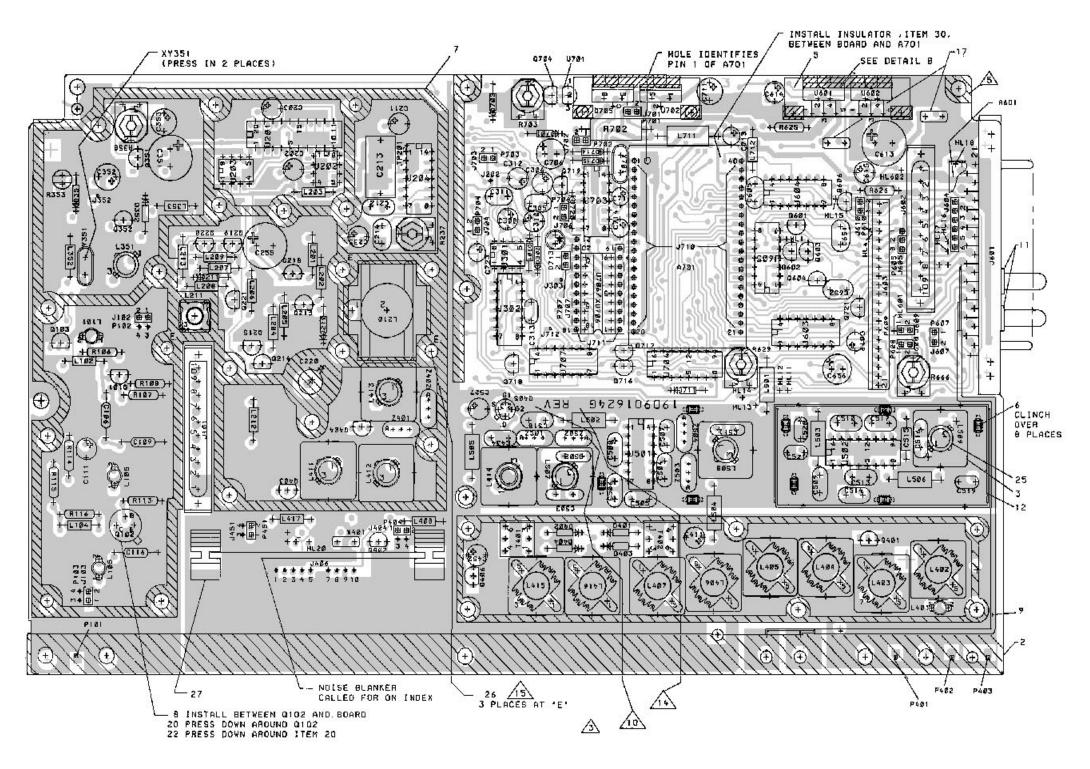
 R32

COMPONENT BOARD (19C851149, Rev. 6) (19A703549, Sh. 2, Rev. 2)

29.7-50 MHz TRANSMIT/RECEIVER SYSTEM BOARD

> (19D901624, Sh. 2, Rev. 3) (19A704621, Sh. 3, & 4, Rev. 3)

COMPONENT SIDE



29.7-50 MHz TRANSMIT/RECEIVER SYSTEM BOARD

(19D901624, Sh. 1, Rev. 9)

(19A704621, Sh. 1 & 2, Rev. 3)



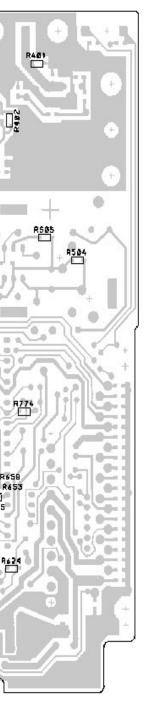
09A08 3YOM38 01 −A 0NA +A A30J08 R(25 R424 1484 9420 R429 R429 R426 8427 R112 R5Ø2 R40 R219 8 8 8 8 8 8 221 0 20 0 -0 R419 R412 100 miles 0 0 R415 .0 84<u>1</u>4 R729 -0 R727 Second I \$00° 6 20 R73 R739 R233 R189 R185 BB742 2002 R231 R316 R. R315 R. R3260 P104 R193 R746 R229 8 **₽**242 92 R361 R24 R775 R204 655 ន្ថិរា R313 22 R723 R236 R656 722 R224 32 R304 A385 287 [] R210 A312 8223 1280 R701 R721 ř. ₫ĝ R356 R778 R213 R77' R202 R62 2 2 8622 R785 8789 R621



OUTLINE DIAGRAM

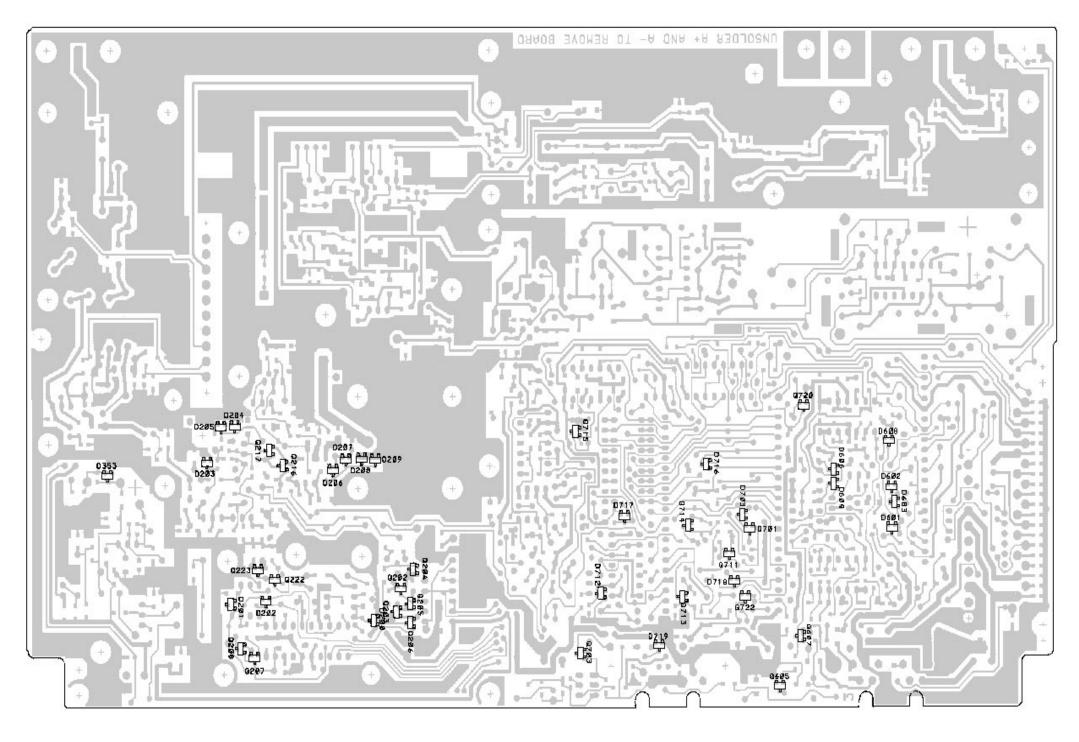


LBI-31535



29.7-50 MHz TRANSMIT/RECEIVER SYSTEM BOARD

(19D901624, Sh. 4, Rev. 3) (19A704621, Sh. 3, & 4, Rev. 3)



CHIP DIODE AND TRANSISTOR LOCATION

29.7-50 MHz TRANSMIT/RECEIVER SYSTEM BOARD (19D901624, Sh. 3, Rev. 2)

(19A704621, Sh. 3, & 4, Rev. 3)



29.7-50 MHz TRANSMIT/RECEIVE/SYSTEM BOARD 19D901630G1 29.7-36 MHz 19D901630G2 36-42 MHz 19D901630G3 42-50 MHz 19D901630G4 29.7-36 MHz (Gold Contacts) 19D901630G5 36-42 MHz (Gold Contacts) 19D901630G6 42-50 (Gold Contacts) SYMBOL PART NUMBER DESCRIPTION ---- ASSEMBLIES ----A1 System Board 19D901624G1 29.7 MHz-36 MHz 19D901624G2 36 MHz-42 MHz 19D901624G3 42 MHz-50 MHz 19D901624G4 29.7 MHz-36 MHz (Gold Contacts) 19D901624G5 36 MHz-42 MHz (Gold Contacts) 19D901624G6 42 MHz-50 MHz (Gold Contacts) ----- CAPACITORS -----C101 19A702052P14 Ceramic: 0.01 µF ±10%, 50 VDCW. C102 19A702052P5 Ceramic: 1000 pF ±10%, 50 VDCW. 19A702052P14 Ceramic: 0.01 µF ±10%, 50 VDCW. C103 thru C105 C106 19B800590P27 Ceramic: 39 pF ±5%, 50 VDCW; OPPM temp coef. (Used in G1 and G4). 19B800590P25 Ceramic: 33 pF ±5%, 50 VDCW; OPPM C106 temp coef. (Used in G2 and G5). C106 19B800590P23 Ceramic: 27 pF ±5%, 50 VDCW; OPPM temp coef. (Used in G3 and G6). C107 19A702052P14 Ceramic: 0.01 µF ±10%, 50 VDCW. and C108 C109 19B800590P639 Ceramic: 128 pF ±5%, 50 VDCW, temp coef -220 +700 PPM. (Used in G1 and G4). Ceramic: 100 pF ±5%, 50 VDCW, C109 19B800590P637 temp coef -220+700 PPM. (Used in G2 and G5). C109 19B800590P633 Ceramic: 68 pF ±5%, 50 VDCW: +350 -1000 PPM temp coef. (Used in G3 and G6). C110 19A702052P14 Ceramic: 0.01 µF ±10%, 50 VDCW. 19A701534P7 Tantalum: 10 µF ±20%, 16 VDCW C111 19A702052P14 Ceramic: 0.01 µF ≟10%, 50 VDCW. C113 C116 19B800590P629 Ceramic: 47 pF ±5%, 50 VDCW, temp coef -150 PPM. (Used in G1 and G4). 19B800590P27 Ceramic: 39 pF ±5%, 50 VDCW; C116 OPPM temp coef. (Used in G2, G3 G5 and G6). 19A702052P5 Ceramic: 1000 pF ±10%, 50 VDCW. C117 and C118 -____ JACKS ____ J101 19B800555G3 Connector: metering, block. Includes: (10) 19A700237P1 contacts. J102 19A703248P1 Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3). Post: Gold Plated, 10 mm length. 19A703248P11 J102 (Used in G4, G5 and G6). Post: Tin Plated, 10 mm length. 19A703248P1 J103 (Used in G1, G2 and G3), J103 19A703248P11 Post: Gold Plated, 10 mm length (Used in G4, G5 and G6).

SYMBOL PART NUMBER DESCRIPTION SYMBOL PART NUMBER H212CRP133C R116 L101 19B800937P10 Coil, RF: 0.115 nH; sim to Paul Smith SK-887-1. H212CBP139C B116 L102 19A700024P11 Coil, RF: 680 nH ±10%. (Used in G1 and G4). B117 9B800607P102 19A700024P10 Coil, RF: 560 nH ±10%. (Used in G2, L102 thru G3, G5 and G6). R119 L103 9B801084P12 Coil, RF: sim to Paul Smith SK917-1. (Used in G1 and G4). L103 9B800937P10 Coil, RF: 0.115 nH; sim to Paul Smith C202 9A701534P7 SK-887-1 (Used in G2, G3, G5 and G6). and 9A700024P17 Coil, RF: 2.2 µH ±10%. C203 L104 C204 19A702061P69 Coil, RF: 0.090 nH; sim to Paul Smith L105 19B800937P8 SK-887-1. C205 I9A702061P93 -----PLUGS -----19A702061P99 C206 P101 19A701785P3 Contact, electrical. P102 19A702104P1 Connector: Shorting Jumper, Tin Plated. C207 9A702052P20 (Used in G1, G2 and G3). C209 9A702061P99 Connector: Shorting Jumper, Gold P102 19A702104P2 Plated. (Housing Color: White). (Used in G4, G5 and G6). 9A702052P20 C210 Connector: Shorting Jumper, Tin Plated. P103 19A702104P1 C211 9A701534P7 (Used in G1, G2 and G3). C212 T644ACP333K P103 19A702104P2 Connector: Shorting Jumper, Gold C213 9A703232P2 Plated. (Housing Color: White). (Used in G4, G5 and G6). C214 9A702250P113 C215 I9A702052P20 ---- TRANSISTORS ----and 9A702084P2 C216 Q101 Silicon, NPN: sim to MPS 2369. C217 9A702061P65 19J706357P1 Silicon, NPN; sim to Type 2N4427. Q102 Q103 19A700022P2 Silicon, PNP: sim to 2N3906. C217 9A702061P61 ---- RESISTORS -----Metal film: 120 ohms ±5%, 1/8 w R101 9B800607P121 C217 9A702061P57 R102 19B800607P510 Metal film: 51 ohms ±5%. 1/8 w. C218 9A702236P38 R103 19B800607P121 Metal film: 120 ohms ±5%, 1/8 w R104 9B800607P103 Metal film: 10K ohms ±5%, 1/8 w. 9A702061P21 C219 and R105 C220 19A134227P5 H212CRP212C R106 Deposited carbon: 1.2K ohms ±5%, 1/4 w. C221 19A702236P44 R107 H212CRP210C Deposited carbon: 1K ohms ±5%, 1/4 w C222 9A702061P99 R108 H212CRP110C Deposited carbon: 100 ohms ±5%, 1/4 w. 9A702052P20 C223 R109 19B800607P222 Metal film: 2.2K ohms ±5%, 1/8 w. C224 19A702052P14 R110 19B800607P103 Metal film: 10K ohms ±5%, 1/8 w. C225 9A702061P93 thru R112 19A702061P7 C227 H212CRP018C R113 Deposited carbon: 18 ohms ±5% 1/4 w. (Used in G1, G2, G4 and G5). C228 19A702061P99 R113 H212CRP022C Deposited carbon: 22 ohms ±5% thru 1/4 w. (Used in G3 and G6). C230 R114 H212CRP018C C232 Deposited carbon: 18 ohms ±5%, 9A702061P1 1/4 w. 19A701534P7 C233 R115 C234 19A702061P5 R116 H212CRP127C Deposited carbon: 270 ohms ±5%, 1/4 w. (Used in G1 and G4). C235 9A702061P45

★ COMPONENTS, ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

PARTS LIST

DESCRIPTION

Deposited carbon: 330 ohms ±5%.

Deposited carbon: 390 ohms ±5%,

Metal film: 1K ohms ±5%, 1/8 w

---- CAPACITORS ----

Tantalum: 10 μE ±20%, 16 VDCW.

Ceramic: 220 pF ±5%, 50 VDCW,

Ceramic: 2200 pF ±5%, 50 VDCW,

Ceramic: 1000 pF ±5%, 50 VDCW,

Ceramic: 0.033 µF ±10%, 50 VDCW.

Ceramic: 1000 pF ±5%, 50 VDCW,

Ceramic: 0.033 µF ±10%, 50 VDCW.

Polvester: .033 uF ±10%. 50 VDCW.

Metallized: 1 µF ±10%, 100 VDCW

Polyester: 0.1 µF ±10%, 50 VDCW.

Ceramic: 0.033 µF ±10%, 50 VDCW.

Ceramic: 150 pF ±5%, 50 VDCW, temp

Ceramic: 100 pF ±5%, 50 VDCW, temp

coef 0 ±30 PPM. (Used in G2 and G5).

Ceramic: 82 pF ±5%, 50 VDCW, temp

coef 0 ±30 PPM. (Used in G3 and G6).

Ceramic: 33 pF ±5%, 50 VDCW,

Ceramic: 15 pF ±5%, 50 VDCW,

Variable: 1.5 to 14 pF, 100 VDCW.

Ceramic: 56 pF ±5%, 50 VDCW,

Ceramic: 1000 pF ±5%, 50 VDCW,

Ceramic: 0.033 uF ±10%, 50 VDCW.

Ceramic: 0.01 µF ±10%, 50 VDCW.

Ceramic: 2200 pF ±5%, 50 VDCW,

Ceramic: 3.3 pF ±0.5 pF, 50 VDCW,

Ceramic: 1000 pF ±5%, 50 VDCW,

Ceramic: 1 pF ±0.5 pF, 50 VDCW.

Tantalum: 10 µF ±20%, 16 VDCW.

Ceramic: 2.2 pF ±0.5 pF, 50 VDCW,

coef 0 ±30 PPM. (Used in G1, G2,

Ceramic: 47 pF ±5%, 50 VDCW, temp

emp coef 0 ±30 PPM/°C.

temp coef 0 ±30 PPM/°C.

temp coef 0 ±30 PPM.

emp coef 0 ±120 PPM.

temp coef 0 ±30 PPM/°C.

temp coef 0 ±120 PPM.

G4 and G5).

temp coef 0 ±30 PPM/°C.

temp coef 0 ±30 PPM.

coef 0 ±30 PPM/°C. (Used in G1 and

G4)

Tantalum: 10 µF ±20%, 16 VDCW.

temp coef 0 ±30 PPM/°C.

temp coef 0 ±30 PPM.

temp coef 0 ±30 PPM/°C.

temp coef 0 ±30 PPM/°C.

1/4 w. (Used in G2 and G5).

1/4 w. (Used in G3 and G6).

LBI-31535

CVMDOI		DECODIDITION
SYMBOL	PART NUMBER	DESCRIPTION
C235	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G3 and G6).
C238	19A702061P21	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.
C239	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G1 and G4).
C239	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2, G3, G5 and G6).
C241	19A702061P45	Ceramic: 47 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM, (Used in G1, G2, G4 and G5).
C241	19A702236P44	Ceramic: 56 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G3 and G6).
C244	19A702061P93	Ceramic: 2200 pF ±5%, 50 VDCW, temp coef_0 ±30 PPM.
C245	19A702061P7	Ceramic: 3.3 pF ±0.5 pF, 50 VDCW, temp coef 0 ±120 PPM.
C246 thru C248	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.
C249	19A702061P1	Ceramic: 1 pF ±0.5 pF, 50 VDCW.
C250 and C251	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.
C251	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.
C252	19A702061P99	Ceramic: 1000 pF ±10%, 50 VDCW.
and C254	134702001133	temp coef 0 \pm 30 PPM/°C.
C255	19A701225P8	Electrolytic: 470 μF -10+75%, 16 VDCW, sim to Sprague 5002D477-G016DGIC.
C256	19A702061P29	Ceramic: 22 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G1 and G4).
C256	19A702061P25	Ceramic: 18 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G2 and G5).
C256	19A702061P21	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G3 and G6).
C257	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G1 and G4).
C257	19A702061P29	Ceramic: 22 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G2 and G5).
C257	19A702061P25	Ceramic: 18 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G3 and G6).
C258	19A702052P14	Ceramic: 0.01 μ F ±10%, 50 VDCW.
		DIODES
D200	19A700083P22	Diode, silicon, zener: 5.1 Volt, sim to C5V1LT1.
D201	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
D202	19A703561P2	Silicon, fast recovery (2 diodes in series).
D203 thru D209	19A700085P4	Silicon, capacitive.
D210	19A700047P2	Silicon, 100 mW, continuous dissipation; sim to DO-15.
D211	19A700028P1	Silicon: 75 mA, 75 PIV; sim to 1N4148.

SYMBOL	PART NUMBER	DESCRIPTION		SYMBOL	PA
		JACKS		R203	19
J202	19A703248P1	Post: Tin Plated, 10 mm length.		R204	19
JZUZ	13870324011	(Used in G1, G2 and G3).		R205	19
J202	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).		R206	19
				R207	19
		INDUCTORS		R208	19
L201	19A700024P25	Coil, RF: 10.0 μH ±10%, 3.70 ohms DC res max.		R209	19
thru L209		DC res max.		R210	19 19
L210	19B801055P6	Coil, RF: sim to Standex SK916-1.		R212 R213	19
L210	100001055P5	(Used in G1 and G4). Coil, RF: sim to Standex SK916-1.		R214	19
LZIU	19B801055P5	(Used in G2 and G5).		R215	19
L 2 10	19B801055P4	Coil, RF: sim to Standex SK916-1. (Used in G3 and G6).		R216	19
L211	19B801036P15	Coil, RF: sim to Paul Smith SK918-1.		R217 and	19
		(Used in G1 and G4).		R218	
L211	19B801036P11	Coil, RF: sim to Paul Smith SK918-1. (Used in G2 and G5).		R219	19
L 2 11	19B801036P9	Coil, RF: sim to Paul Smith SK918-1. (Used in G3 and G6).		R220	19
L212	19A700024P10	Coil, RF: 560 nH ±10%.		R221	19
1010	10470003400	(Used in G1 and G4). Coil, RF: 470 nH ±10%.		R222	19
L212	19A700024P9	(Used in G2 and G5).		R223	19
L212	19A700024P8	Coil, RF: 390 nH ±10%.		R224	19
L213	19A700024P12	(Used in G3 and G6). Coil, RF: 820 nH ±10%.		R225	19
LZIJ	19A700024F12	(Used in G1 and G4).		R226 thru	19
L213	19A700024P11	Coil, RF: 680 nH ±10%. (Used in G2 and G5).		R228 R229	19
L213	19A700024P10	Coil, RF: 560 nH ±10%.		R230	19
		(Used in G3 and G6).		R231	19
		TRANSISTORS		R232	19
Q202	19A700059P2	Silicon, PNP: sim to MMBT3906, low		R233	19
thru Q206		profile.		R234	19
Q207	19A700076P2	Silicon, NPN: sim to MMBT3904, low		R236	19
and Q208		profile.		R237	19
0213	19A700060P3	N-Type, field effect; sim to J310.		R238	19
Q214	19A700023P2	Silicon, NPN: sim to 2N3904.		and	
and O215				R239 R240	1.0
Q215 Q216	19A700059P2	Silicon, PNP: sim to MMBT3906, low		R240	18
and		profile.		and	``
Q217 Q218	19A700022P2	Silicon, PNP: sim to 2N3906.		R242 R244	15
Q218	19A700023P2	Silicon, NPN: sim to 2N3904.		R244	19
and	10470002012			R246	19
Q220 Q221	19A700060P3	N-Type, field effect; sim to J310.		R247	1
0222	19A700076P2	Silicon, NPN: sim to MMBT3904, low		R248	19
and	104/000/012	profile.		R249	15
0223				R250	15
					1
R200	19B800607P331	Metai film: 330 ohms ±5%, 1/8 w.			1
R201 and R202	19B800607P100	Metal film: 10 ohms ±5%, 1/8 w.			
		I	L		1

DESCRIPTION PART NUMBER Metal film: 10K ohms ±5%, 1/8 w. 9B800607P103 9B800607P510 Metal film: 51 ohms ±5%, 1/8 w. 9B800607P100 Metal film: 10 ohms ±5%, 1/8 w. Metal film: 4.7K ohms ±5%, 1/8 w. 19B800607P472 9B800607P510 Metal film: 51 ohms ±5%, 1/8 w. 9B800607P224 Metal film: 220K ohms ±5%, 1/8 w. Metal film: 47K ohms ±5%, 1/8 w. 9B800607P473 9B800607P681 Metal film: 680 ohms ±5%, 1/8 w. Metal film: 10 ohms ±5%, 1/8 w. 19B800607P100 19B800607P273 Metal film: 27K ohms ±5%, 1/8 w. 19B800607P223 Metal film: 22K ohms ±5%, 1/8 w. 19B800607P152 Metal film: 1.5K ohms ±5%, 1/8 w. Metal film: 100K ohms ±5%, 1/8 w. 19B800607P104 98800607P273 Metal film: 27K ohms ±5%, 1/8 w. 19A702931P141 Metal film: 261 ohms ±1%, 200 VDCW, 1/8 w. 19B800607P180 Metal film: 18 ohms ±5%, 1/8 w. 19A702931P141 Metal film: 261 ohms ±1%, 200 VDCW, 1/8 w. Metal film: 150 ohms ±5%, 1/8 w. 19B800607P151 Metal film: 150K ohms ±5%, 1/8 w. 19B800607P154 19B800607P103 Metal film: 10K ohms ±5%, 1/8 w. 19B800607P682 Metal film: 6.8K ohms ±5%, 1/8 w. 19B800607P103 Metal film: 10K ohms ±5%, 1/8 w. 19B800607P121 Metal film: 120 ohms ±5%, 1/8 w. 19B800607P683 Metal film: 68K ohms ±5%, 1/8 w. Metal film: 820 ohms ±5%, 1/8 w. 19B800607P821 Metal film: 100 ohms ±5%, 1/8 w. 19B800607P101 19B800607P152 Metal film: 1.5K ohms ±5%, 1/8 w. 19B800607P182 Metal film: 1.8K ohms ±5%, 1/8 w. Metal film: 32.4K ohms ±1%, 200 19A702931P350 VDCW, 1/8 w. 19B800784P108 Variable: 10K ohms ±20%, 1/2 w. 19B800607P683 Metal film: 68K ohms ±5%, 1/8 w. 19B800607P121 Metal film: 120 ohms ±5%, 1/8 w. 19B800607P103 Metal film: 10K ohms ±5%, 1/8 w. Metal film: 1.8K ohms ±5%, 1/8 w. 19B800607P182 Metal film: 1.5K ohms ±5%, 1/8 w. 19B800607P152 Metal film: 820 ohms ±5%, 1/8 w. 19B800607P821 19B800607P101 Metal film: 100 ohms ±5%, 1/8 w. Metal film: 1.8K ohms ±5%, 1/8 w. 9B800607P182 Metal film: 820 ohms ±5%, 1/8 w. 19B800607P821 19B800607P152 Metal film: 1.5K ohms ±5%, 1/8 w.

PARTS LIST

					DECODIDEION
SYMBOL	PART NUMBER	DESCRIPTION	SYMBOL	PART NUMBER	DESCRIPTION
		INTEGRATED CIRCUITS			jacks
U201	19B800902P4 19A703091P1	Digital: Synthesizer, CMOS Serial input. Digital: /64, /65 Prescaler; sim to	J303	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
U202		MČ12017P.	J303	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).
U203 U204	19J706579P2 19A700029P44	Comparator. Sim to LM311. Digital: BILATERAL SWITCH.	J352	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
		CAPACITORS	J352	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).
C302	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.			
C304	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	L351	19C850701P101	Coil, RF: variable, wire size No. 34 AWG.
C305	19A702250P212	Polyester: 0.68 μF ±5%, 50 VDCW.	L352	19A700024P22	Coil, RF: 5.6 μH ±10%.
C306	19A701534P7	Tantalum: 10 μF ±20%, 16 VDCW.	L353	19A700024P29	Coil, RF: 22 μ H ±10%.
C307	19A702052P28	Ceramic: 0.022 µF ±10%, 50 VDCW.			
C308	19A701534P7	Tantalum: 10 μF ±20%, 16 VDCW.			TRANSISTORS
C309	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.	Q351	19A700023P2	Silicon, NPN: sim to 2N3904.
C310	19A701534P7	Tantalum: 10 μF ±20%, 16 VDCW.	Q352	19A700060P3	N-Type, field effect; sim to J310.
C311	19A702250P211	Polvester: 0.47 µF ±5%, 50 VDCW.			RESISTORS
C312	19A701534P7	Tantalum: $10 \mu\text{F} \pm 20\%$, 16 VDCW.			
C312	T644ACP268J	Polyester: .0068 µF ±5%, 50 VDCW.	R301	19B800607P473	Metal film: 47K ohms ±5%, 1/8 w.
C313	19A702061P25	Ceramic: 18 pF ±5%, 50 VDCW,	R302	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
		temp coef 0 ±30 PPM/°C.	R303	19A702931P303	Metal film: 10.5K ohms ±1%, 200 VDCW, 1/8 w.
C351	19A701225P3	Electrolytic: 220 µF, -10+50%, 25 VDCW.	R304	19B800607P472	Metal film: 4.7K ohms ±5%, 1/8 w.
C352	19A701534P9	Tantalum: 47 μ F ±20%, 6.3 VDCW.	R305	19A702931P212	Metal film: 1300 ohms ±1%, 200 VDCW, 1/8 w.
C353	19A701534P8	Tantalum: 22 μF ±20%, 16 VDCW.	R306	19B800607P272	Metal film: 2.7K ohms ±5%, 1/8 w.
C354	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	R307	19B800607P273	Metal film: 27K ohms ±5%, 1/8 w.
C355	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	R308	19A702931P278	Metal film: 6340 ohms ±1%, 200 VDCW, 1/8 w.
C356	19A702236P40	Ceramic: 39 pF ±5%, 50 VDCW,	R309	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
6350	1347022301 40	temp coef 0 ±30 PPM.	R310	19B800607P331	Metal film: 330 ohms ±5%, 1/8 w.
C357	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	R31 1	19A702931P369	Metal film: 51.1K ohms ±1%, 200 VDCW, 1/8 w.
C358	19A702061P57	Ceramic: 82 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.	R312	19A702931P303	Metal film: 10.5K ohms ±1%, 200 VDCW, 1/8 w.
C359	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.	R313	19A702931P278	Metal film: 6340 ohms ±1%, 200 VDCW, 1/8 w.
C360	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	R314	19A702931P330	Metal film: 20K ohms ±1%, 200 VDCW, 1/8 w.
C361	19A702052P20	Ceramic: 0.033 μ F ±10%, 50 VDCW.	R315	19A702931P310	Metal film: 12.4K ohms ±1%, 200 VDCW, 1/8 w.
C362 and C363	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	R316	19A702931P350	Metal film: 32.4K ohms ±1%, 200 VDCW, 1/8 w.
C364	19A702061P29	Ceramic: 22 pF ±5%, 50 VDCW,	R317	19B800607P222	Metal film: 2.2K ohms ±5%, 1/8 w.
		temp coef 0 ±30 PPM.	R318	19B800607P105	Metal film: 1M ohms ±5%, 1/8 w.
		DIODES	R351	19B800607P393	Metal film: 39K ohms ±5%, 1/8 w.
D301	19A702015P1	Silicon; sim to IN458A.	R352	19B800607P273	Metal film: 27K ohms ≠5%, 1/8 w.
and D302			R353	19A701828P5	Thermistor: 3.3K ohms ±5%; sim to Midwest ID2299.
D351	19A700028P1	Silicon: 75 mA, 75 PIV; sim to 1N4148.	R354	19B800607P183	Metal film: 18K ohms ±5%, 1/8 w.
and D352			R355	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
D353	19A700085P3	Silicon, capacitive.	R356	19B800607P683	Metal film: 68K ohms ±5%, 1/8 w.
0000			R357	19B800607P471	Metal film: 470 ohms ±5%, 1/8 w.
			R358	19B800784P108	Variable: 10K ohms ±20%, 1/2 w.

14

PARTS LIST

SYMBOL	PART NUMBER	DESCRIPTION	SYMBOL	PART NUMBER	DESCRIPTION				
Data	100000070000	Matal films 22K above - EW - 179 st	C412	19A702061P7	Ceramic: 3.3 pF ±0.5 pF, 50 VDCW,	SYM	1BOL	PART NUMBER	DESCRIPTION
R359 R360	19B800607P223 19B800607P820	Metal film: 22K ohms ±5%, 1/8 w. Metal film: 82 ohms ±5%, 1/8 w.	Ç412	19A/02061F7	temp coef 0 ±120 PPM. (Used in G1 and G4).		423 ·	19A702052P24	Ceramic: 0.068 µF ±10%, 50 VDCW.
R361 R362	19B800607P681 19B800607P683	Metal film: 680 ohms ±5%, 1/8 w. Metal film: 68K ohms ±5%, 1/8 w.	C412	19A702061P5	Ceramic: 2.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G2		424 425	19A702061P11	Ceramic: 6.8 pF ±0.5 pF, 50 VDCW,
R363	198800607P181	Metal film: 180 ohms ±5%, 1/8 w.			and G5).				temp coef 0 ±60 PPM.
R364	19B800607P100	Metal film: 10 chms ±5%, 1/8 w.	C412	19A702061P4	Ceramic: 1.8 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 250 PPM. (Used in G3 and G6).	ar	426 nd 427	19A702052P24	Ceramic: 0.068 µF ±10%, 50 VDCW.
R365	19A702931P318	Metal film: 15K ohms ±1%, 200 VDCW, 1/8 w.	C413	19A702236P44	Ceramic: 56 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G1 and			19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.
		INTEGRATED CIRCUITS -			G4).	C	429	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.
U301 U302	19A700086P4 19A700029P44	Linear: Dual Op Amp; sim to 4558. Digital: BILATERAL SWITCH.	C413	19A702236P40	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2 and G5).	C4	430	19A702061P10	Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM.
		SOCKETS	C413	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G3 and G8).	C.	431	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW,
XY351	19A702742P1	Crystal socket.	C414	19A702061P6	Go,. Ceramic: 2.7 pF ±0.5 pF, 50 VDCW,		400	40470000004	temp coef 0 ±30 PPM/°C.
		CAPACITORS	C414	19A702001F0	temp coef 0 ±120 PPM. (Used in G1	_		19A702052P24	Ceramic: 0.068 μF ±10%, 50 VDCW.
					and G4).		433	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.
C403	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.	C414	19A702061P4	Ceramic: 1.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±250 PPM. (Used in G2	C	434	T644ACP333K	Polyester: .033 μF ±10%, 50 VDCW.
C404	19A702061P71	Ceramic: 270 pF ±5%, 50 VDCW, temp			and G5).	C4	435	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
0404	198702001173	coef 0 ±30 PPM/°C. (Used in G1 and	C414	19A702061P3	Ceramic: 1.5 pF ±0.5 pF, 50 VDCW,	C.	436	19A702052P20	Ceramic: 0.033 µF ±10%, 50 VDCW.
		G4).			temp coef 0 ± 250 PPM. (Used in G3 and G6).	C .	437	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp
C404	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G2, G3, G5 and G6).	C415	19A702236P44	Ceramic: 56 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G1 and				coef 0 ±30 PPM/°C. (Used in G1 and G4).
C405	19A702236P46	Ceramic: 68 pF ±5%, 50 VDCW, temp coef 0 PPM ±30 PPM. (Used in G1 and	C415	19A702236P40	G4). Ceramic: 39 pF ±5%, 50 VDCW, temp		:437	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G2, G3, G5 and G6).
C405	19A702236P42	G4). Ceramic: 47 pF ±5%, 50 VDCW, temp	C415	19A702236P38	coef 0 ±30 PPM. (Used in G2 and G5). Ceramic: 33 pF ±5%, 50 VDCW, temp	C.	438	19A702061P1	Ceramic: 1 pF \pm 0.5 pF, 50 VDCW. (Used in G1 and G4).
C405	19A702236P40	coef 0 ±30 PPM. (Used in G2 and G5). Ceramic: 39 pF ±5%, 50 VDCW, temp			coef 0 ±30 PPM/°C. (Used in G3 and G6).	C.	:438	19A702061P4	Ceramic: 1.8 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 250 PPM. (Used in G2 and G5).
C406	19A702061P8	coef 0 ±30 PPM. (Used in G3 and G6). Ceramic: 3.9 pF ±0.5 pF, 50 VDCW,	C416	19A702061P9	Ceramic: 4.7 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1 and G4).	c	438	19A702061P2	Ceramic: 1.2 pF ±0.5 pF, 50 VDCW,
		temp coef 0 \pm 120 PPM. (Used in G1 and G4).	C416	19A702061P7	Ceramic: 3.3 pF ±0.5 pF, 50 VDCW, tempcoef 0 ±120 PPM. (Used in G2				temp coef 0 \pm 250 PPM. (Used in G3 and G6).
C406	19A702061P6	Ceramic: 2.7 pF ±0.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G2 and G5).	C416	19A702061P6	and G5). Ceramic: 2.7 pF ±0.5 pF, 50 VDCW,		:439	19A702236P38	Ceramic: 33 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM/°C. (Used in G3 and G6).
C406	19A702061P5	Ceramic: 2.2 pF ±0.5 pF, 50 VDCW,	Ç418	194702001F6	temp coef 0 ±120 PPM. (Used in G3 and G6).	c	:439	19A702236P40	Ceramic: 39 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G1, G2, G4
		temp coef 0 \pm 120 PPM. (Used in G3 and G6).	C417	19A702061P61	Ceramic: 100 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G1 and G4).		:440	19A702061P69	and G5). Ceramic: 220 pF ±5%, 50 VDCW, temp
C407	19A702236P44	Ceramic: 56 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G1 and G4).	C417	19A702236P44	Ceramic: 56 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM/°C. (Used in G2 and			1347020011 00	coef 0 ±30 PPM/°C. (Used in G1 and G4).
C407	19A702236P40	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2 and G5).	C417	19A702061P45	G5). Ceramic: 47 pF ±5%, 50 VDCW, temp	C	:440	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2, G3, G5 and G6).
C407	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G3 and	C418	19A702061P63	coef 0 ±30 PPM. (Used in G3 and G6). Ceramic: 120 pF ±5%, 50 VDCW, temp		C441 hru	19A702052P14	and Go). Ceramic: 0.01 μF ±10%, 50 VDCW.
C408	19A702052P14	G6). Ceramic: 0.01 μF ±10%, 50 VDCW.	C418	19A702061P57	coef 0 ±30 PPM. (Used in G1 and G4). Ceramic: 82 pF ±5%, 50 VDCW, temp	Ċ	444	104709050094	Ceramic: 0.068 μF ±10%, 50 VDCW.
C408 C409	19A702052P14	Ceramic: 10 pF ±5%, 50 VDCW,			coef 0 \pm 30 PPM. (Used in G2 and G5).			19A702052P24	
C409	19A702236P44	temp coef 0 ±30 PPM. Ceramic: 56 pF ±5%, 50 VDCW, temp	C418	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G3 and G6).			19A702061P13	Ceramic: 10 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM.
C410	104702230544	coef 0 ±30 PPM/°C. (Used in G1 and G4).	C419 and	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	ar	2450 ind 2451	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
C410	19A702236P40	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2 and G5).	C420 C421	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp			19A701534P7 19A702052P24	Tantalum: 10 μF ±20%, 16 VDCW. Ceramic: 0.068 μF ±10%, 50 VDCW.
C410	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G3 and	C422	19A702061P45	coef 0 ±30 PPM/°C. Ceramic: 47 pF ±5%, 50 VDCW, temp	th	2453 hru 2456	187702002124	Contracting, 0,000 pr = 10 /0, 00 40 C44.
C411	19A701534P7	G6). Tantalum: 10 μF ±20%, 16 VDCW.			coef 0 ±30 PPM.	c	2457	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.

S١

SYMBOL	PART NUMBER	DESCRIPTION
C461	19A702061P3	Ceramic: 1.5 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 250 PPM. (Used in G1 and G4).
C462	19A702061P33	Ceramic: 27 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM/°C. (Used in G2 and G5).
D401 thru D404	19A700047P4	Silicon, Schottky: 100 Mw.
		JACKS
J404	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
J404	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).
J406	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).
J406	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
J451	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
J451	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).
L401	198801084P10	Coil, RF: sim to Paul Smith SK917-1.
L402	19C851187P800	Coil, RF: sim to Paul Smith SK923-1. (Used in G1, G2, G4 and G5).
L402	19C851187P700	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L403	19C851187P810	Coil, RF: sim to Paul Smith SK923-1. (Used in G1, G2, G4 and G5).
L403	19C851187P711	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L404	19C851187P800	Coil, RF: sim to Paul Smith SK923-1. (Used in G1, G2, G4 and G5).
L404	19C851187P700	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L405	19C851187P800	Coil, RF: sim to Paul Smith SK923-1. (Used in G1, G2, G4 and G5).
L405	19C851187P700	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L406	19C851187P800	Coil, RF: sim to Paul Smith SK923-1. (Used in G1, G2, G4 and G5).
L406	19C851187P700	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L407	19C851187P800	Coil, RF: sim to Paul Smith SK923-1. (Used in G1, G2, G4 and G5).
L407	19C851187P700	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L408	19A700024P33	Coil, RF: 47 μH ±10%.
L409	19A705470P35	Coil, Fixed: 6.8 μH ±20%.
L410	19A705470P37	Coil, Fixed.
L411 thru L414	19C850701P101	Coil, RF: variable, wire size No. 34 AWG.
L414 L415	19C851187P811	Coll, RF: sim to Paul Smith SK923-1.
L415	19C851187P710	(Used in G1 and G4). Coil, RF: sim to Paul Smith SK923-1. (Used in G2 and G5).

SYMBOLI	PART NUMBER	DESCRIPTION
L415	19C851187P610	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L416	19C851187P800	Coil, RF: sim to Paul Smith SK923-1. (Used in G1 and G4).
L416	19C851187P700	Coil, RF: sim to Paul Smith SK923-1. (Used in G2 and G5).
L416	19C851187P600	Coil, RF: sim to Paul Smith SK923-1. (Used in G3 and G6).
L417	19A700024P15	Coil, RF: 1.5 μH ±10%.
		PLUGS
P401 thru P403	19A701785P3	Contact, electrical.
P404	19A702104P2	Connector; Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).
P404	19A702104P1	Connector: Shorting Jumper, Tin Plated. (Used in G1, G2 and G3).
P451	19A702104P1	Connector: Shorting Jumper, Tin Plated. (Used in G1, G2 and G3).
P451	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).
		TRANSISTORS
Q401 and Q402	19A700060P3	N-Type, field effect; sim to J310.
Q403 and Q404	19A134137P6	N-Type, field effect.
Q405	19A116818P3	N Channel, field effect; sim to Type 3N1877.
Q406	19A701808P2	Silicon, NPN; sim to MPS 6595.
		RESISTORS
R401	19B800607P473	Metal film: 47K ohms ±5%, 1/8 w.
R402	19B800607P221	Metal film: 220 ohms ±5%, 1/8 w.
R403	19B800607P272	Metal film: 2.7K ohms ±5%, 1/8 w.
R404	19B800607P390	Metal film; 39 ohms ±5%, 1/8 w.
R405	19B800607P221	Metal film; 220 ohms ±5%, 1/8 w.
R406	19B800607P272	Metal film: 2.7K ohms ±5%, 1/8 w.
R407 and R408	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
R409	19B800607P332	Metal film: 3.3K ohms ±5%, 1/8 w.
R410	19A702931P273	Metal film: 5620 ohms ±1 %, 200 VDCW, 1/8 w.
R411	19B800607P332	Metal film: 3.3K ohms ±5%, 1/8 w.
R412	19A702931P273	Metal film: 5620 ohms ±1 %, 200 VDCW, 1/8 w.
R413	19B800607P681	Metal film: 680 chms ±5%, 1/8 w.
R414	19B800607P272	Metal film: 2.7K ohms ±5%, 1/8 w.
R415	19B800607P223	Metal film; 22K ohms ±5%, 1/8 w.
R416	19B800607P153	Metal film: 15K ohms ±5%, 1/8 w.
R417	19B800607P221	Metal film: 220 ohms ±5%, 1/8 w.
R418	19B800607P510	Metal film: 51 ohms ±5%, 1/8 w.
R419	19B800607P272	Metal film: 2.7K ohms ±5%, 1/8 w.

SYMBOL	PART NUMBER	DESCRIPTION
R420	19B800607P100	Metal film: 10 ohms ±5%, 1/8 w.
R423	19B800607P182	Metal film: 1.8K ohms ±5%, 1/8 w.
R424	19B800607P181	Metal film: 180 ohms ±5%, 1/8 w.
R425	19B800607P220	Metal film: 22 ohms ±5%, 1/8 w.
R426	19B800607P821	Metal film: 820 ohms ±5%, 1/8 w. {Used in G1 and G4}.
R426	19B800607P221	Metal film: 220 ohms ±5%, 1/8 w. (Used in G2, G3, G5 and G6).
R427	19B800607P821	Metal film: 820 ohms ±5%, 1/8 w. (Used in G1 and G4).
R427	19B800607P221	Metal film: 220 ohms ±5%, 1/8 w. (Used in G2, G3, G5 and G6).
R428	19B800607P821	Metal film: 820 ohms ±5%, 1/8 w. (Used in G1 and G4).
R428	19B800607P221	Metal film: 220 ohms ±5%, 1/8 w. (Used in G2, G3, G5 and G6).
R429	19B800607P821	Metal film: 820 ohms ±5%, 1/8 w. (Used in G1 and G4).
R429	19B800607P221	Metal film: 220 ohms ±5%, 1/8 w. (Used in G2, G3, G5 and G6).
R430 and R431	19B800607P104	Metal film: 100K ohms ±5%, 1/8 w.
		—————————————————————
T401 and T402	19B801143P1	Transformer, Balun.
		CABLES
W401	19B800890P1	Coil, RF: 9.5 nH ±5%; sim to Paul Smith SK-896-1.
		FILTER
Z401	19A702068G1	Crystal, filter: 4 pole, 2 coupled-dual crystals.
C501	19A702061P10	Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM.
C502	19A700235P21	Ceramic: 47 pF ±5%, 50 VDCW.
C503	19A700235P24	Ceramic: 82 pF ±5%, 50 VDCW.
C504 thru C510	T644ACP333K	Polyester: .033 μF ±10%, 50 VDCW.
C511	19A700235P21	Ceramic: 47 pF ±5%, 50 VDCW.
C512	19A702061P57	Ceramic: 82 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.
C513 and C514	T644ACP333K	Polyester: .033 μF ±10%, 50 VDCW.
C515	19A700013P10	Phenolic: 0.56 pF ±5%, 500 VDCW.
C516	19A701624P132	Ceramic: 100 pF ±5%, 500 VDCW, temp coef 0 ±30 PPM.
C517 and C518	T644ACP333K	Polγester: .033 μF ±10%, 50 VDCW.
C519	T644ACP215K	Polyester: .0015 μF ±10%, 50 VDCW.
C520 and C521	T644ACP310K	Polyester: .010 μF ±10%, 50 VDCW.

PARTS L	IST	
1	SYMBOL	PART NUMBER
	C522 and C523	19A702052P20

SYMBOL	PART NUMBER	DESCRIPTION	SYMBOL	PART NUMBER	DESCRIPTION
C522 and C523	19A702052P20	Ceramic: 0.033 μF ±10%, 50 VDCW.	C614 and C615	19A701534P7	Tantalum: 10 μF ±20%, 16 VDCW.
C524	19A702052P24	Ceramic: 0.068 µF ±10%, 50 VDCW.	C616	19A702052P22	Ceramic: 0.047 µF ±10%, 50 VDCW.
C525	19A702061P10	Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM.	thru C618		
C526	19A702061P3	Ceramic: 1.5 pF ±0.5 pF, 50 VDCW,	C619	19A701534P3	Tantalum: 0.47 μF ±20%, 35 VDCW.
		temp coef 0 ±250 PPM.	C620	19A702052P2	2Ceramic: 0.047 μF ±10%, 50 VDCW.
C527	19A701534P7	Tantalum: 10 μF ±20%, 16 VDCW.	C621	19A702052P3	Ceramic: 470 pF ±10%, 50 VDCW.
			C651 and C652	19A702250P113	Polyester: 0.1 μF ±10%, 50 VDCW.
L501 thru L506	19A701761P45	Coil, RF: 68 uh ±10%, 3.30 ohms DC res max.	C656	19A701225P1	Electrolytic: 15 µF -10 +75%, 25 VDCW; sim to Sprague 501D156-G025BB1C.
L507 and L508	19C850701P101	Coil, RF: variable, wire size No. 34 AWG,	C658 thru	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.
L509	19C850701P102	Coil, RF: variable, wire size No. 34 AWG.	C678 C682 thru	19A702052P3	Ceramic: 470 pF ±10%, 50 VDCW.
0704	4047000010141	———— RESISTORS ———— Metal film: 261 ohms ±1%, 200	C684		
R501	19A702931P141	VDCW, 1/8 w.	Daat	40470050100	
R502	19B800607P182	Metal film: 1.8K ohms ±5%, 1/8 w.	D601	19A703561P2	Silicon, fast recovery (2 diodes in series).
R503	19A702931P141	Metal film: 261 ohms ±1%, 200 VDCW, 1/8 w.	D602	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
R504	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.	D603	19A703561P2	Silicon, fast recovery
R505	19B800607P472	Metal film: 4.7K ohms ±5%, 1/8 w.	D D D D	10170005000	(2 dicdes in series). Silicon: 2 Diodes in Series;
R507	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.	D604	19A700053P2	sim to BAV99.
R508 R509	19B800607P472 19B800607P681	Metal film: 4.7K ohms ±5%, 1/8 w. Metal film: 680 ohms ±5%, 1/8 w.	D606 thru D608	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
		INTEGRATED CIRCUITS			JACKS
U501	19A700044P1	Linear, IF Amplifier & Detector; sim to ULN2111A.	1004	10005050101	
U502	19A700091P1	Linear, IF Amplifier & Detector; sim to CA3089E.	J601	19C850591G4 19A701246G2 19A701254P1 19A701254P2 C	Connector. Includes: Shell; Connector; onnector.
		FILTER	J602	19B800555G4	Connector: metering, red. Includes (1) 19A700237P1 contacts.
Z501	19A702068G3	Crystal filter.	J603	19A700072P47	Printed wire: 21 contacts rated at
Z503	19A702068G3	Crystal filter. — SYSTEM/AUDIO/SQUELCH —			2 1/2 amps per contact; sim to Molex 22-27-2211. (Used in G1, G2 and G3).
A601	19C851003P1	Printed Wire Board.	J603	19A704852P47	Printed wire: 21 contacts rated @ 2 1/ amps; sim to Molex 22-29-2211.
C601	19A702052P6	— — — — CAPACITORS — — — Ceramic: 1500 pF ±10%, 50 VDCW.	J604	19B801421P1	(Used in G4, G5 and G6). Cable, flat: 6 contacts, sim to UL Style 2651.
thru C603			J605	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
C604	19A702052P22	Ceramic: 0.047 μF ±10%, 50 VDCW. Polvester: 0.1 μF ±10%, 50 VDCW.	J605	19A703248P11	Post: Gold Plated, 10 mm length.
C605 C606	19A702250P113 19A702052P14	Ceramic: 0.01 μ F ±10%, 50 VDCW.	J607	19A703248P11	(Used in G4, G5 and G6). Post: Gold Plated, 10 mm length.
thru C609					(Used in G4, G5 and G6).
C610	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.	J607	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).
C611 C612	19A702052P22 19A702052P20	Ceramic: 0.047 μF ±10%, 50 VDCW. Ceramic: 0.033 μF ±10%, 50 VDCW.	J608	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).
C612 C613	19A702032F20	Electrolytic: 220 µF, -10+50%,	J608	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).

PARTS LIST

SYMBOL	PART NUMBER	DESCRIPTION	SYMBOL	PART NUMBER	DESCRIPTION	SYMBOL	PART NUMBER	DESCRIPTION
J609	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	R614	19A702931P355	Metal film: 36.5K ohms ±1%, 200 VDCW. 1/8 w.	C3	19A702061P21	Ceramic: 15 pF ±5%, 50 VDCW,
J609	19A703248P1	Osed in G4, G5 and G5). Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).	R615	19A702931P293	Metal film: 9090 chms ±1%, 200 VDCW, 1/8 w.	C4	19A702061P65	temp coef 0 ±30 PPM. (Used in G12). Ceramic: 150 pF ±5%, 50 VDCW, temp
and J610			R616	19A702931P369	Metal film: 51.1K ohms ±1%, 200	C6	19A702061P65	ccef 0 ±30 PPM/°C. (Used in G12). Ceramic: 150 pF ±5%, 50 VDCW, temp
J610	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	and R617		VDCW, 1/8 w.	Св	19A702061P61	coef 0 ±30 PPM/°C. (Used in G12). Ceramic: 100 pF ±5%, 50 VDCW, temp
		PLUG\$	R618	19B800607P104	Metal film: 100K ohms ±5%, 1/8 w.	65	138702001101	coef 0 ±30 PPM. (Used in G12).
P605	19A702104P1	Connector: Shorting Jumper, Tin	R619	19B800607P124	Metal film: 120K ohms ±5%, 1/8 w.	C10	19A702061P61	Ceramic: 100 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G12).
		Plated. (Used in G1, G2 and G3).	R620	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w. Metal film: 680 ohms ±5%, 1/8 w.	C12	19A702061P13	Ceramic: 10 pF ±5%, 50 VDCW, temp
P605	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White).	R621	19B800607P681 19B800607P330	Metal film: 33 ohms ±5%, 1/8 w.	thru	19A702081F13	coef 0 ±30 PPM. (Used in G12).
		(Used in G4, G5 and G6).	R622 R623	19B800607P390	Metal film: 39 ohms ±5%, 1/8 w.	C19		
P607	19A702104P1	Connector: Shorting Jumper, Tin	R624	19B800607P152	Metal film; 1.5K ohms ±5%, 1/8 w.	C21 thru	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G12).
_		Plated. (Used in G1, G2 and G3).	R625	H212CRP947C	Deposited carbon: 4.7 ohms ±5%,	C24		
P607	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).	and R626	1212011 0470	1/4 w.	C26 and C27	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW. (Used in G12).
P608	19A702104P1	Connector: Shorting Jumper, Tin Plated.	R627	19B800607P154	Metel film: 150K ohms ±5%, 1/8 w.	C28	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
		(Used in G1, G2 and G3).	R628	19B800607P822	Metal film: 8.2K ohms ±5%, 1/8 w.	and C29		(Used in G12).
P608	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).	R629	19B800784P111	Variable, conductive: 100K ohms ±20%, 0.33 w max.	C30 and	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C, (Used in G12).
P609	19A702104P1	Connector: Shorting Jumper, Tin Plated.	R630	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.	C31		
P609	19A702104P2	(Used in G1, G2 and G3). Connector: Shorting Jumper, Gold	R631 and R632	19B800607P104	Metal film: 100K ohms ±5%, 1/8 w.	C32	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW. (Used in G12).
		Plated, (Housing Color: White). (Used in G4, G5 and G6).	R633	19B800607P102	Metal film: 1K ohms ±5%, 1/8 w.	C33	19A702061P69	Ceramic: 220 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM/°C. (Used in G12).
P610	19A702104P1	Connector: Shorting Jumper, Tin Plated. (Used in G1, G2 and G3).	R651 and R652	19B800607P561	Metal film: 560 ohms ±5%, 1/8 w.	C34	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G12).
P610	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used	R653 thru	19B800607P103	Metal film: 10K chms ±5%, 1/8 w.	C35	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW. (Used in G12).
		in G4, G5 and G6).	R658			C36	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G12).
		———— TRANSISTORS ———	R659	19B800607P472	Metal film: 4.7K ohms ±5%, 1/8 w.	C37	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
Q601	19A700023P2	Silicon, NPN: sim to 2N3904.	R660	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.	thru C39		(Used in G12).
thru Q604			R661	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.	C39 C40	19A702052P24	Ceramic: 0.068 µF ±10%, 50 VDCW.
Q605	19A700076P2	Silicon, NPN: sim to MMBT3904, low	R662	19B800607P473	Metal film: 47K ohms ±5%, 1/8 w.	040	130702032124	(Used in G12).
Q606	19A700023P2	profile. Silicon, NPN: sim to 2N3904.	R663 and R664	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.			———— RESISTORS ————
		RESISTORS	R665	19B800607P224	Metal film: 220K ohms ±5%, 1/8 w.	81	198800607P101	Metal film: 100 ohms ±5%, 1/8 w. (Used in G12).
R601	19A702931P318	Metal film: 15K ohms ±1%, 200 VDCW, 1/8 w.	R666	19B800784P108	Variable: 10K ohms ±20%, 1/2 w. — — INTEGRATED CIRCUITS — —	R4	198800607P101	Metal film: 100 ohms ±5%, 1/8 w. (Used in G12).
R602	19A702931P273	Metal film: 5620 ohms ±1%, 200 VDCW, 1/8 w.	U601	19A701830P1	Linear: Audio Power Amplifier;	R6	19B800607P101	Metal film; 100 ohms ±5%, 1/8 w. (Used in G12).
R603	19A702931P393	Metal film: 90.9K chms ±1%, 200 VDCW, 1/8 w.	and U602		sim to TDA2003.	R7	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w. (Used in G12).
R604	19B800607P472	Metal film: 4.7K ohms ±5%, 1/8 w.	U603	19A701789P1	Linear: Quad Op Amp; sim to LM324.	R21 thru	19B800607P101	Metal film: 100 ohms ±5%, 1/8 w. (Used in G12).
R605	19B800607P822	Metal film: 8.2K chms ±5%, 1/8 w.	and			R24		
R606	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.	U604	104700000844	Digital: BILATERAL SWITCH.	R26	19B800607P100	Metal film: 10 ohms ±5%, 1/8 w.
R607	19B800607P104	Metal film: 100K ohms ±5%, 1/8 w.	U605	19A700029P44	5	R27	1988006072103	(Used in G12). Metal film: 10K ohms ±5%, 1/8 w.
R608	19B800607P334	Metal film: 330K ohms ±5%, 1/8 w.	A701		Microcomputer Component Board 19C851149G12	R27	130000077103	(Used in G12). $(Used in G12)$.
R609	198800607P103	Metal film: 10K ohms ±5%, 1/8 w.				R28	19B800607P101	Metal film: 100 ohms ±5%, 1/8 w.
R610	19B800607P154	Metal film: 150K ohms ±5%, 1/8 w.			CAPACITORS	thru R31		(Used in G12).
R611	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.	C1	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.	R32	19B800607P103	Metal film: 10K chms ±5%, 1/8 w.
R612 R613	19B800607P124 19B800607P223	Metal film: 120K ohms ±5%, 1/8 w. Metal film: 22K ohms ±5%, 1/8 w.	C2	19A702061P13	(Used in G12). Ceramic: 10 pF ±5%, 50 VDCW, temp			(Used in G12).
1013	1900000/7223	HAD LOF SHIEL ZZIN UTITIS ZU /U, T/U W.			coef 0 ±30 PPM. (Used in G12).			

SY

SYMBOL PART NUMBER		DESCRIPTION		
R33 and R34	19B800607P101	Metal film: 100 ohms ±5%, 1/8 w. (Used in G12).		
R35	19B800607P272	Metal film: 2.7K ohms ±5%, 1/8 w. (Used in G12).		
R36 thru R39	19B800607P101	Metal film: 100 ohms ±5%, 1/8 w. (Used in G12).		
		INTEGRATED CIRCUITS		
U1	19A703244P23	Digital: MICROCOMPUTER, HMOS, 8-bit. (Used in G12).		
		CAPACITORS		
C701 thru C703	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.		
C704	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.		
C705	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.		
C706	19A703893P10	Electrolytic: 200 μF -10+50%, 10 VDCW.		
C708	19A702052P20	Ceramic: 0.033 μF ±10%, 50 VDCW.		
C710	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.		
C711	19A701534P8	Tantalum: 22 μF ±20%, 16 VDCW.		
C712	19A702052P20	Ceramic: 0.033 μF ±10%, 50 VDCW.		
C713	19A701534P4	Tantaium: 1 μF ±20%, 35 VDCW.		
C714	19A701534P3	Tantalum: 0.47 µF ±20%, 35 VDCW.		
C716	19A701534P4	Tantalum: 1 μF ±20%, 35 VDCW.		
C717	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.		
C718	19A702052P22	Ceramic: 0.047 µF ±10%, 50 VDCW.		
C719	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.		
C720	19A702052P20	Ceramic: 0.033 µF ±10%, 50 VDCW.		
C722	19A702052P20	Ceramic: 0.033 μF ±10%, 50 VDCW.		
C723	19A701534P4	Tantalum: 1 μF ±20%, 35 VDCW.		
C724	19A702052P24	Ceramic: 0.068 µF ±10%, 50 VDCW.		
C725	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.		
C727	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.		
C728	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.		
D701	19A700025P2	Silicon, zener: 400 mW max; sim to BZX55-C2V7.		
D702	19A700028P1	Silicon: 75 mA, 75 PIV; sim to 1N4148.		
D703	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.		
D711	19A700047P2	Silicon, 100 mW, continuous dissipation; sim to DO-15.		
D712	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.		
D713	162B3011P0002	Light Emitting Diode: Red; sim to GE 22L-2.		
D714	19A700025P3	Silicon, zener: 400 mW max; sim to BZX55-C3V3.		
D715	19A700025P8	Silicon, zener: 400 mW max; sim to BZX55-C6V8.		

PARTS LIST	

SYMBOL	PART NUMBER	DESCRIPTION	SYMBOL	PART NUM
D716 thru D719	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.	P704	19A702104P
D720	19A700047P2	Silicon, 100 mW, continuous dissipation; sim to DO-15.	P706	19A702104P
		JACKS	P706	19A702104P
J701	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).	and 9707	13/10/2104
J701	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	P707	19A702104P
J702	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).		
J702	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	Q70 1	19A700076P
J703	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).	Q703	19A700076P
J703	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	Q704	19A702503P
J704	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).	Q705 Q711	19A116375P 19A700076P
J704	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	Q713	19A700076P
J706	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	and Q714	
J706 and	19A703248P1	Post: Tin Plated, 10 mm length. (Used in G1, G2 and G3).	Q715	19A700059P
J707			Q716 thru	19A700023P
J707	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	Q719 Q720	19A700076P
J710	19A703248P13	Post: Gold Plated, 16 mm length. (Used in G4, G5 and G6).	0721	19A700023P
J710	19A703248P3	Post: Tin Plated, 16 mm length. (Used in G1, G2 and G3).	Q721	19A700023P
J711	19A703248P4	Post: Tin Plated, 19 mm length. (Used in G1, G2 and G3).		
J711	19A703248P14	Post: Gold Plated, 19 mm length. (Used in G4, G5 and G6).	R701	19B800607P
J712	19A703248P1	Post: Tin Plated, 10 mm length.	R702	19A700112P
1740	104702040044	(Used in G1, G2 and G3).	R703	19B800784P
J712	19A703248P11	Post: Gold Plated, 10 mm length. (Used in G4, G5 and G6).	R704	19A702931P
		INDUCTORS	R705	19A702931P
L711	19A700000P25	Coil, RF: 15 μH ±10%; sim to Jeffers 4421-9K.	R706	19B800607P
L712	19A700024P21	Coil, RF, fixed: 4.7 μH ±10%; sim to	R707	19B800607P
		Jeffers 4436-8K.	R708	19B800607P
		PLUGS	R709	19B800607P
P701	19A702104P2	Connector: Shorting Jumper, Gold	R710	19B800607P
.,	10,00210112	Plated. (Housing Color: White). (Used	R711	198800607P
		in G4, G5 and G6).	R713	19B800607P
P701 and	19A702104P1	Connector: Shorting Jumper, Tin Plated. (Used in G1, G2 and G3).	R714	19B800607P
P702			R715	19B800607P
P702	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used	R716	19B800607P
and P703		in G4, G5 and G6).	R717	19B800607P
P703	19A702104P1	Connector: Shorting Jumper, Tin	R718	19B800607P
and P704		Plated. (Used in G1, G2 and G3).	R719 R720	19B800607P
				1.0000000

MBOL	PART NUMBER	DESCRIPTION
P704	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).
P706	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).
P706 and P707	19A702104P1	Connector: Shorting Jumper, Tin Plated. (Used in G1, G2 and G3).
P707	19A702104P2	Connector: Shorting Jumper, Gold Plated. (Housing Color: White). (Used in G4, G5 and G6).
		TRANSISTORS
2701	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
2703	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
2704	19A702503P2	Silicon, NPN: sim to 2N4401.
2705	19A116375P1	Silicon, PNP.
2711	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
2713 and 2714	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
2715	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
2716 thru 2719	19A700023P2	Silicon, NPN: sim to 2N3904.
2720	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
2721	19A700023P2	Silicon, NPN: sim to 2N3904.
2722	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
R701	19B800607P152	Metal film: 1.5K ohms ±5%, 1/8 w.
R702	19A700112P43	Composition: 150 ohms ±5%, 1 w.
7703	19B800784P108	Variable: 10K ohms ±20%, 1/2 w.
7704	19A702931P179	Metal film: 649 ohms ±1%, 200 VDCW, 1/8 w.
7705	19A702931P141	Metal film: 261 chms ±1%, 200 VDCW, 1/8 w.
R706	19B800607P681	Metal film: 680 chms \pm 5%, 1/8 w.
7707	19B800607P152	Metal film: 1.5K ohms ±5%, 1/8 w.
R708	19B800607P223	Metal film: 22K ohms ±5%, 1/8 w.
R709	19B800607P101	Metal film: 100 ohms ±5%, 1/8 w.
7710	19B800607P331	Metal film: 330 ohms ±5%, 1/8 w.
7711	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
7713	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
R714	19B800607P101	Metal film: 100 ohms ±5%, 1/8 w.
7715	19B800607P473	Metal film: 47K ohms ±5%, 1/8 w.
R 716	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
R717	19B800607P473	Metal film: 47K ohms ±5%, 1/8 w.
R718	19B800607P103	Metal film: 10K ohms ±5%, 1/8 w.
R719	19B800607P822	Metal film: 8.2K ohms ±5%, 1/8 w.
7720	19B800607P104	Metal film: 100K ohms ±5%, 1/8 w.

SCHEMATIC DIAGRAM

	TABLE	OF CONTENTS						
NUTES & CHARTS 1								
SECTION. SYSTEM 10								
	<u>-</u> FUNCT10		CPNT Eries					
	SYSTEN INT	ERCONNECT	600					
	SYSTEMZAUDIO	SOUELCH		2				
	FUNCTIO	<u>IH</u> <u>5</u>	CPNT <u>Eries</u>					
			600					
	AUDIO SQUELCH Régulator		600 600 700					
	HEBOLATOR		700					
			CPNT	3				
	FUNCTIO		ERIES					
		A CONTROL	700					
	RECEIVER		CPNT	4				
	FUNCTIO		ERIES					
	RF/MIXER/] (f AMP	T PREAMP	400 500					
	TRANSMITTER	DRIVER		- 5				
	FUNCTIO		ERIES					
	EXCITER AUDIO PROC		100 300					
	SYNTHESIZER		CPNT	- 6				
FUNCTION SERVES								
				- 7				
REFERENCE OSCILLATOR7 CPNT Function Series								
	REF OSCILL		350					
]				
	GP1.4 29.7-36 MHz	GP2,5 36-42 MHz	GP3.6 42-50 MHz					
C106 C109		33-	27# 68#	-				
C116 C2)7		39 P 100 P	39e 82e	-]				
CZ35		47m	33e	1				
C239 C241		t 80 e 47 e	100e 56e	4				
				1				
C25.6 C257		18e 22e	15=	4				
C404	270	220e	220#	1				
CN05 CN06	68- 3.9-	4/= 2.7=	39-	4				
C407	56+	396	33P	1				
C410	56	39+	33F	-				
C412 C413	3.3r 56r	2.2	33-	-				
Ċ414	2.7	ł.8r	1.5=	1				
C445 C416	56r 4.7r	39#	33#	-				
C417	100e		47e	1				
C418	120e	BZP	100	4				
C437 C438	33# 1#	27# 1,8P	27#	1				
E439	398	39=	33#	1				
CA40 C461	220# 1,5e	100e	100+	4				
C462	1,38	27 P		1				
L102	480n	560n	560n]				
L103 U212	158n 56មក	115n 470n	115n 390n	-				
L213	_820n	66ûn	560n	1				
F113	18	19	22	4				
A116 R426	270 920	330 220	390 220	1				
8427	8 5U	220	220	1				
R428	820	220	220	1				
R429	820	220	220	1				

NOTES,
A PART OF PVR.
A PART OF MIGHER ASSEMBLY LEVEL.
3. ★ IDENTIFIES "CHIP" COMPONENTS (EXAMPLE: R456*) Which are located on solder Side of P¥0.
A TO ADD NOISE BLANKER OPTION, REMOVE ¥401, AND PLUG TH NOISE BLANKER BOARD INTO J406.
5. \pm indicates vehicular ground
A FOR IMPROVED BX INTERMOD PERFORMANCE (VITHOUT NOISE BLANKER) Remove 0403 and 0404.
8. YOLTAGE READINGS:
ALL VULTAGES ARE TYPICAL, VOLTAGES ARE MEASURED WITH A 20.000 ORM PEA VOLT Meter, reference to a- and not chassis Ground, unless otherwise indicated,
SHEET 2: S - SQUELCHED HECEIVER U - UNSQUELCHED RECEIVER H - RECEIVER MODE (PTT HIGH) T - TRANSMIT MODE (PTT LO)
SHEET 5.6. Voltage Readings are taken with The taansmitter unkeyed/keyed. EX:.45 (unkeyed)/.65 (reyed). A 22 um choke must be used in the hot Meter Lead to avoig detuning RF circuits.
SHEET 3.4.7. Voltage Readings are taken with the Transhitter unkeyed.integrated circuit Voltages are Heasured with a high Input impedance digital voltmeter.
🔊 JUMPER PLUG CONNECTIONS FOR OPTIONS.
THE BOARD IS ASSEMBLED WITH ALL JUMPER PLUGS PRESENT. For Fixed Squelch Option, Move P605 to J605-1 & 2 & Ado R666 (194700105P41. Add Jumper From A601-HL2 to A601-HL10 For Fixed Squelch with 9500 of H11 Type Control Units.
FOR HII INTERFACE OPTION ANO/OR CHANNEL GUARD OPTION, REMOVE P609. WITH Both options also remove p609. For fixed squelch with bual control,remove p605.
A REGULATED +5Y AND +9V CAN BE OPENED BY P701 THRU P704 FOR TROUBLE SHOOTING.
FOR SERIAL LOAD OF EE PROM FROM RADIO FROMI CONNECTOR JOOT JOOT-TO SERIAL CONTROL JOOT-29 STORE JOOT-30 SERIAL DATA JOOT-32 SERIAL CLOCK JOOT-36 RESET
A FUNCTION INTERFACE POINTS PROVIDED FOR DATA INTERFACE.
A STANDARD REFERENCE OSCILLATOR FREQUENCY - 13.2 MHZ.
A PROVIDED FOR TEST/TROUBLE SHOOTING.

AS REMOVE PTO6 TO USE MINI EZ PROM PROGRAMMER. REPLACE THEN PROGRAMMING COMPLETE.

A PTOT DISABLES E² PROM PROGRAMMING FUNCTION AND IS Recommended for \$950 and \$990 control unit applications without download and all other control unit applications. ALL CHIP RESISTORS ARE 1/0 WATT ALL OTHER RESISTORS ARE 1/4 WATT UNLESS OTHERWISE SPECIFIED. Resistor values in a Unless followed by Multiplier 4, or 4. Capacitor values in f Unless followed by Multiplier 4, or or, p. Inductance values in K Unless followed by Multiplier 4, or or 4.

SPARE GATES					
OEVICE	INPUT	OVTPUT	CONTROL		
V605 0	11	10	12		
Ű605A	I	2	13		
U704F	14	13			

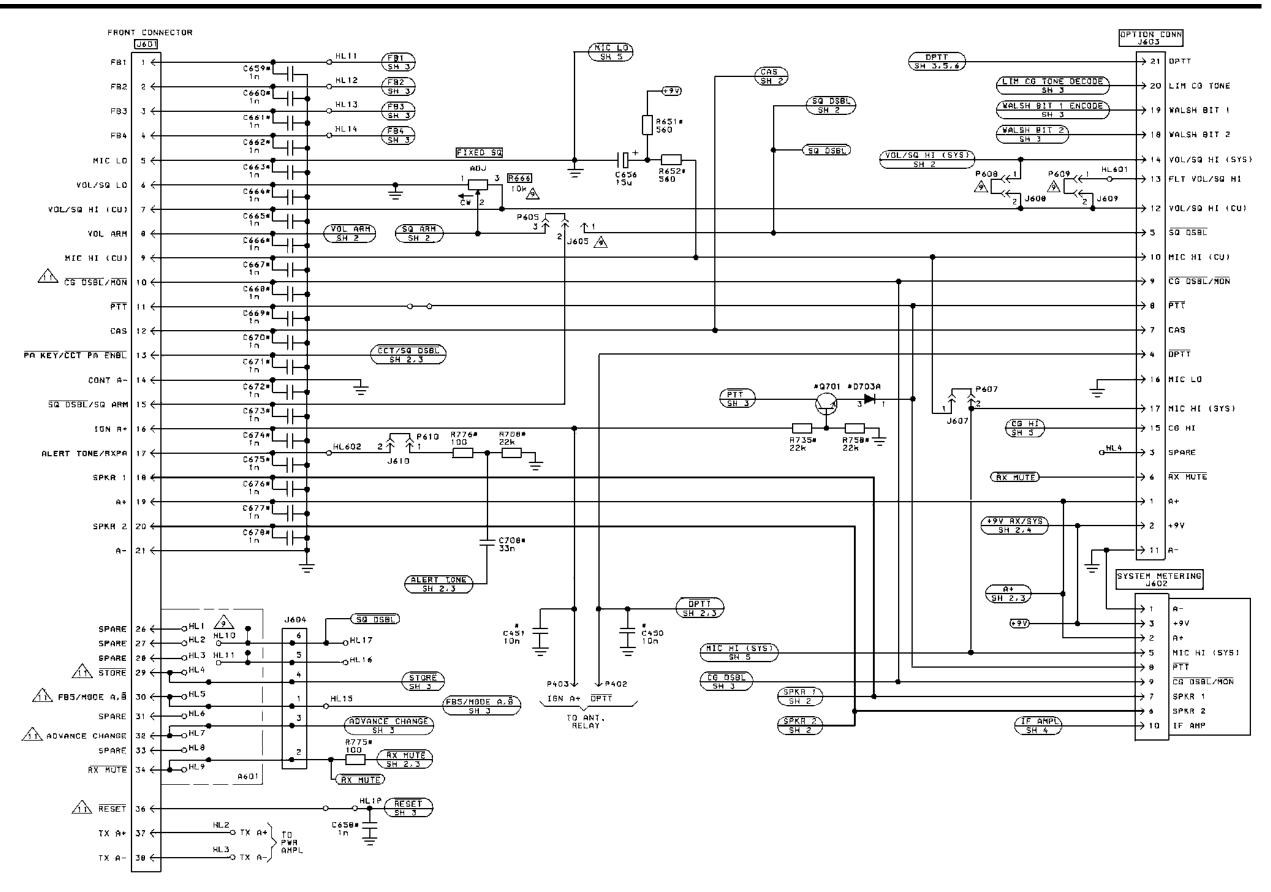
POVER & GADUND CONNECTIONS							
DEVICE	+9V PIN NO.	Я- Pin NO.	+5V PIN NO.				
U203	8	774					
U204	14	7					
V301	8	4					
0302	14	7					
U603	+	11					
U604	4	11					
U&05	14	1.7.11.12.13					
U783		7	14				
U704		8.14	16				
0707		7	14				

MODEL NO.	REV. LETTER	FREQ RANGE	OPTION CONNECTORS
PL19090163061 PL19090162461	F	20.7.7.80	TIN
PL19090163064 PL19090162464	C	29.7-36 MHz	GOLD
PL19D901630G2 PL19D90162462	٤	36-42 MHz	TIN
PL19090163065 PL19090162465	C		GOLD
PL19090163063 PL19090162463	E	42-50 MHz	TIN
PL19090163086 PC19090162466	С		60LB

LBI-31535

29.7-50 MHz RADIO

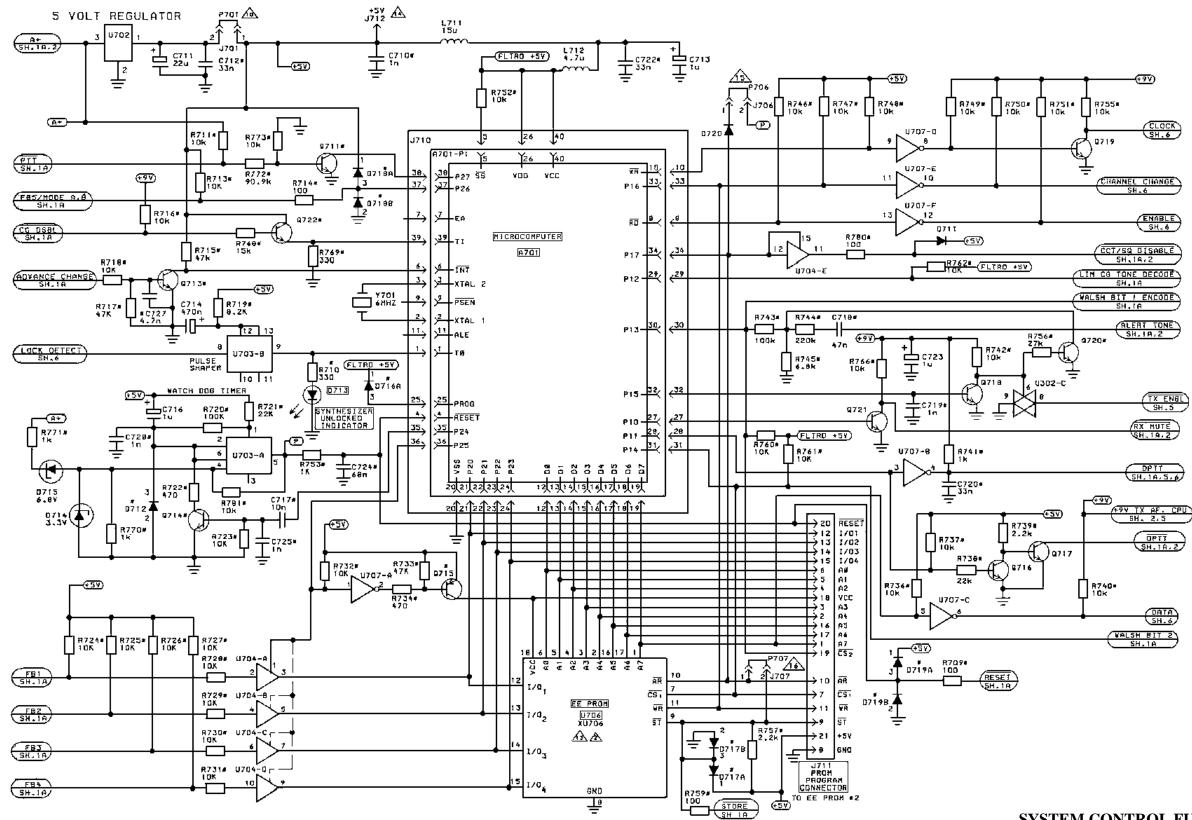
(19D901626, Sh. 1, Rev.8)



(19D901626, Sh. 1A, Rev. 3)

29.7-50 MHz RADIO

SCHEMATIC DIAGRAM

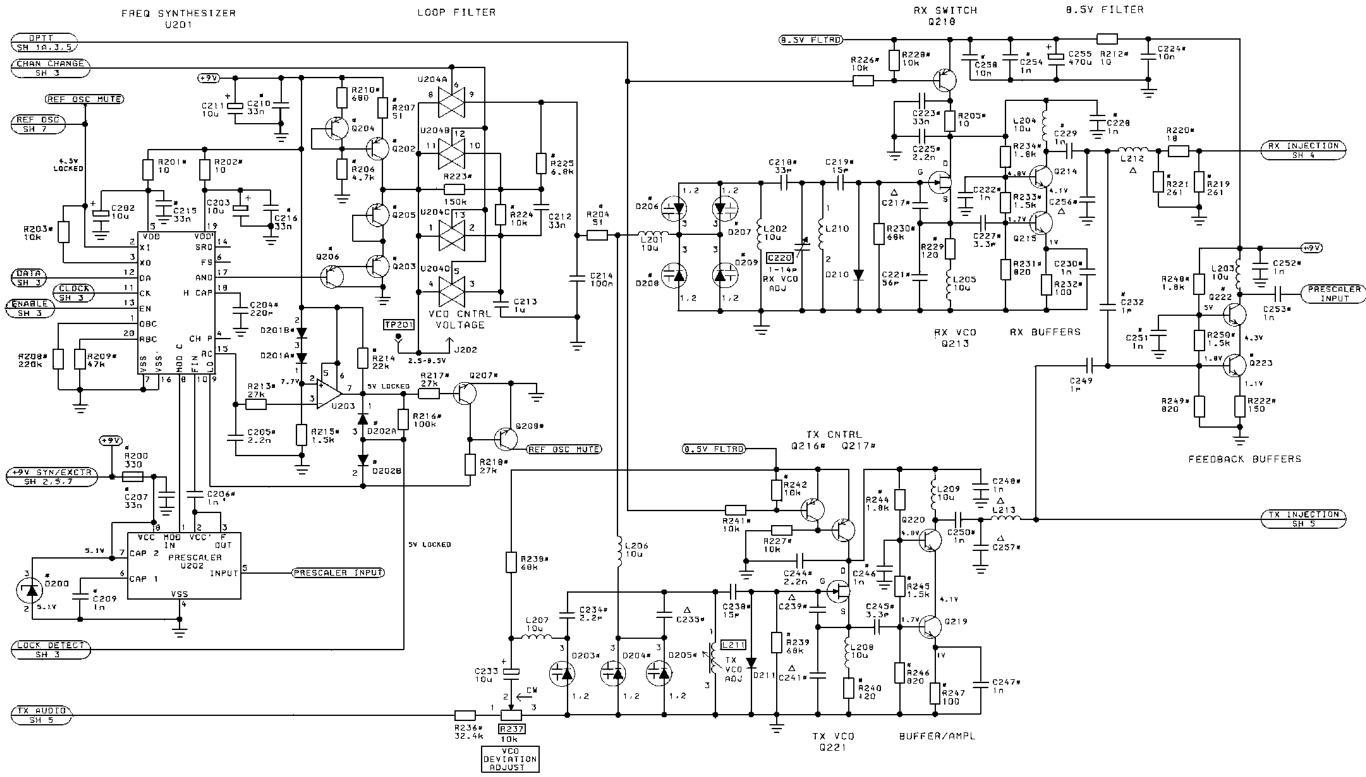


LBI-31535

SYSTEM CONTROL FUNCTIONS

(19D901626, Sh. 3, Rev. 3)

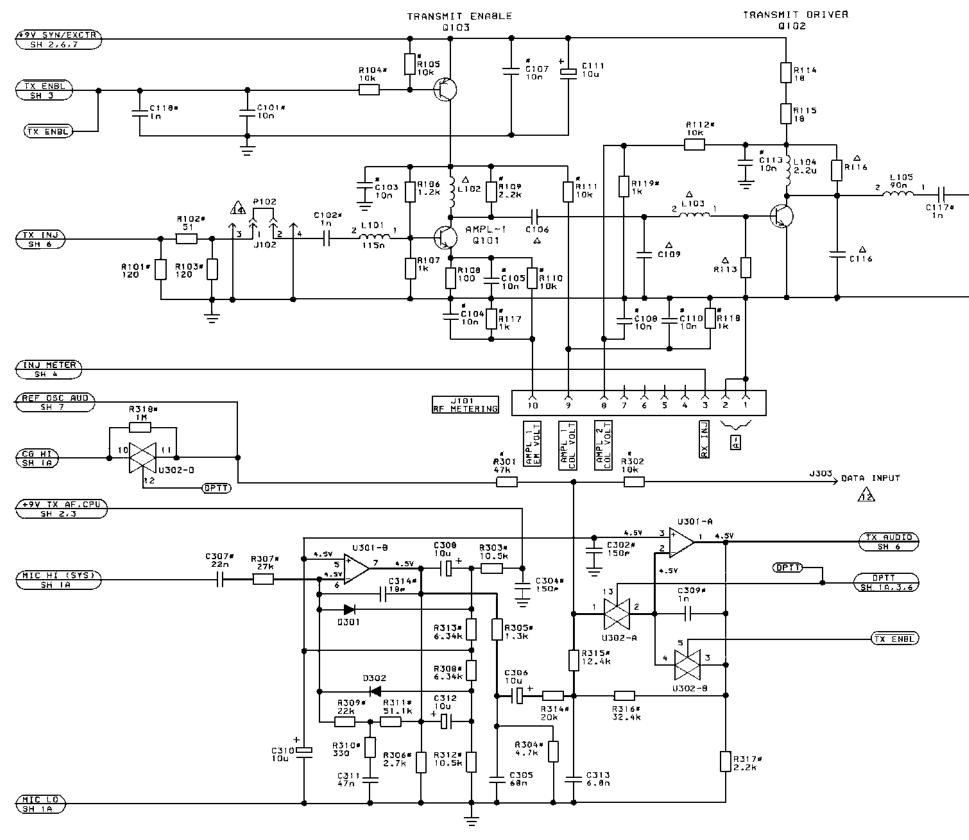
SCHEMATIC DIAGRAM



29.7-50 MHz SYNTHESIZER/VCO

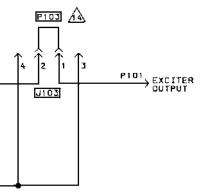
(19D901626, Sh. 6, Rev. 4)

SCHEMATIC DIAGRAM



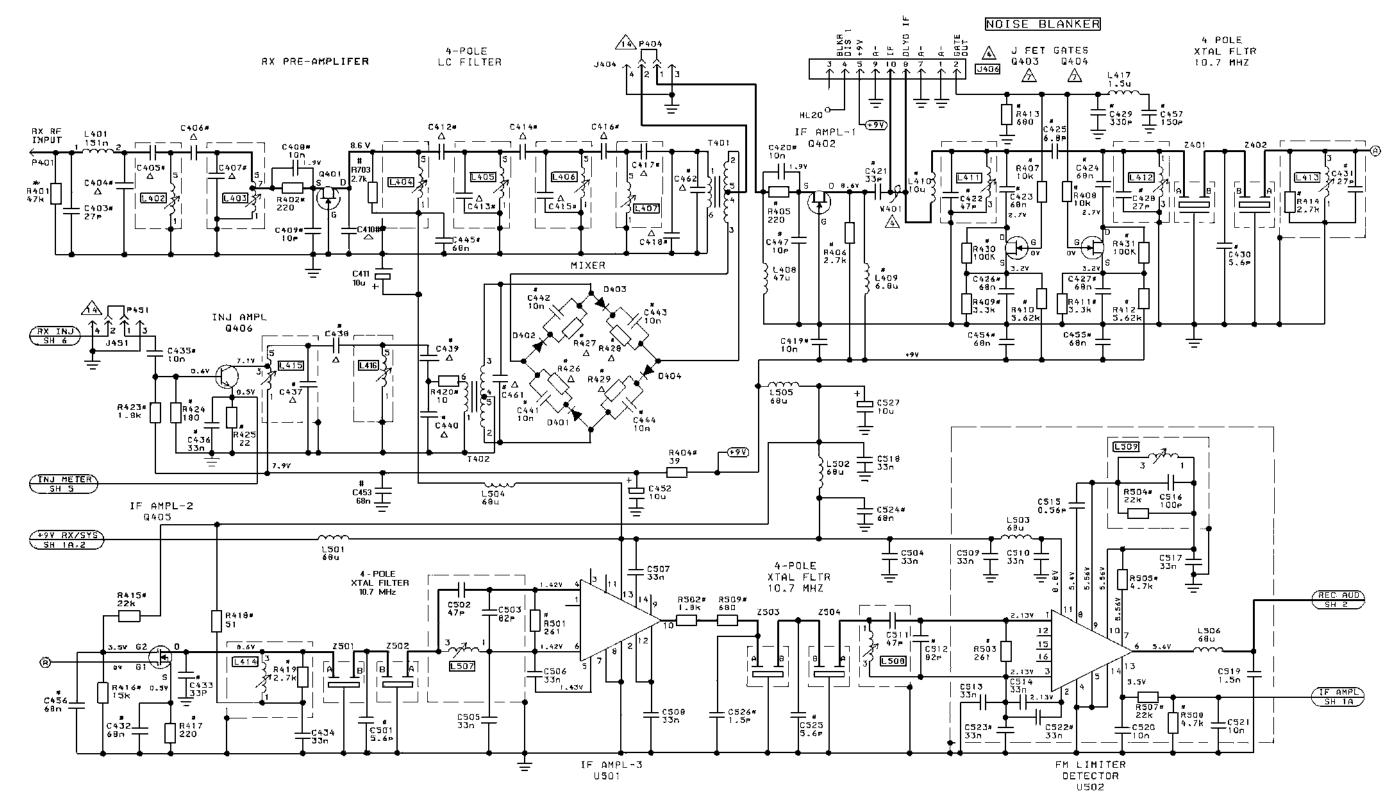
AUDIO PROCESSOR

LBI-31535



29.7-50 MHz TRANSMITTER

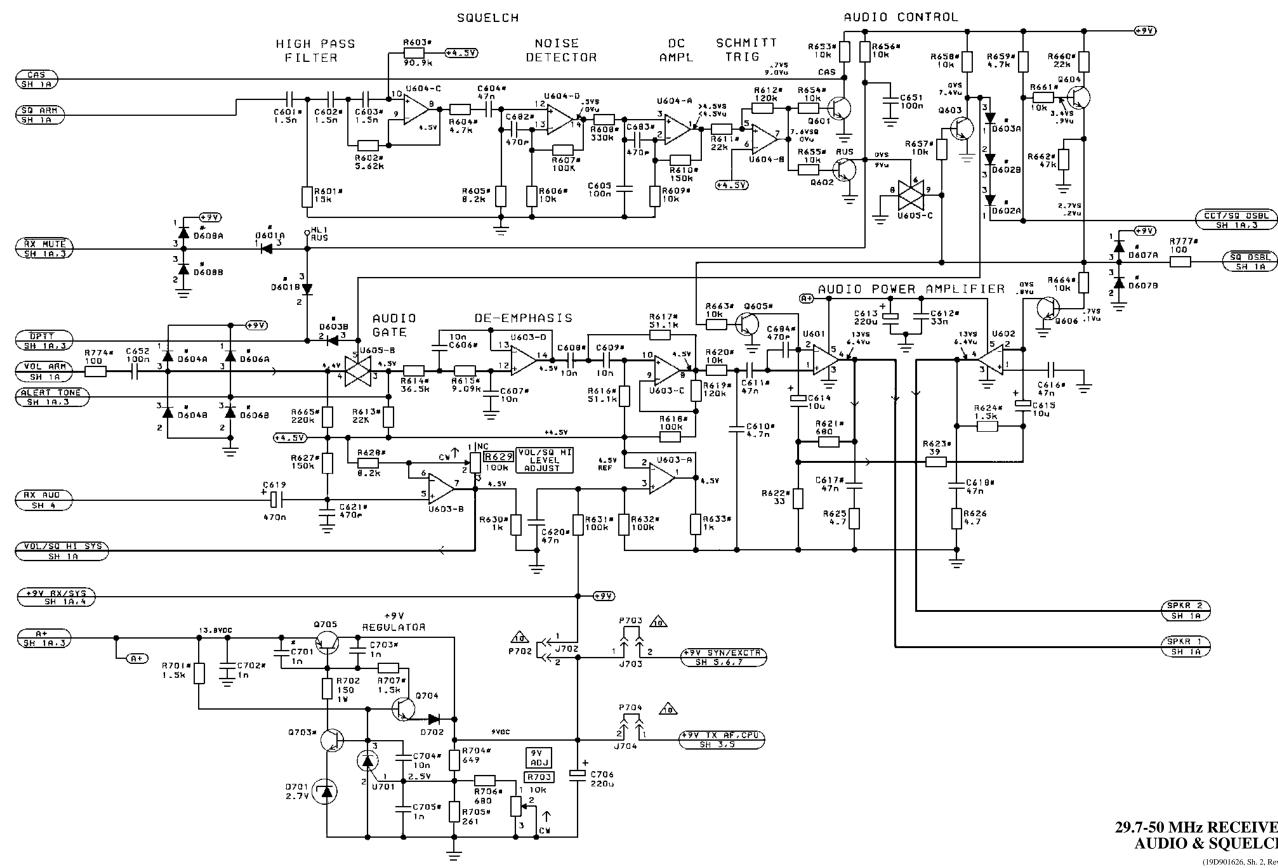
(19D901626, Sh. 5, Rev. 0)



29.7-50 MHz RECEIVER

(19D901626, Sh. 4, Rev. 3)

SCHEMATIC DIAGRAM



LBI-31535

29.7-50 MHz RECEIVER **AUDIO & SQUELCH**

(19D901626, Sh. 2, Rev. 1)